The World's Leading PV And Semiconductor Equipment Supplier

Integrated PV Ingot and Wafer Lines with Enhanced Automation and Productivity

LINTON Technologies Group

CONTENTS

stock code: 920368

01

INTRODUCTION TO LINTON

A Better Linton
A Better Self

Linton Technologies Group

The world's leading PV and semiconductor equipment supplier

COMPANY PROFILE

LINTON

Linton Technologies Group

- ☆ **Founded:** September 2007.
- ☆ **Employees:** **2000+** including 500+ in R&D.
- ☆ **Listed:** Beijing Stock Exchange, Stock Code: 920368.
- ☆ **Acquired Kayex of Rochester, USA (from SPX), in 2013**

  bringing over **70+** years of expertise in **puller design, manufacturing, and crystal growth.**

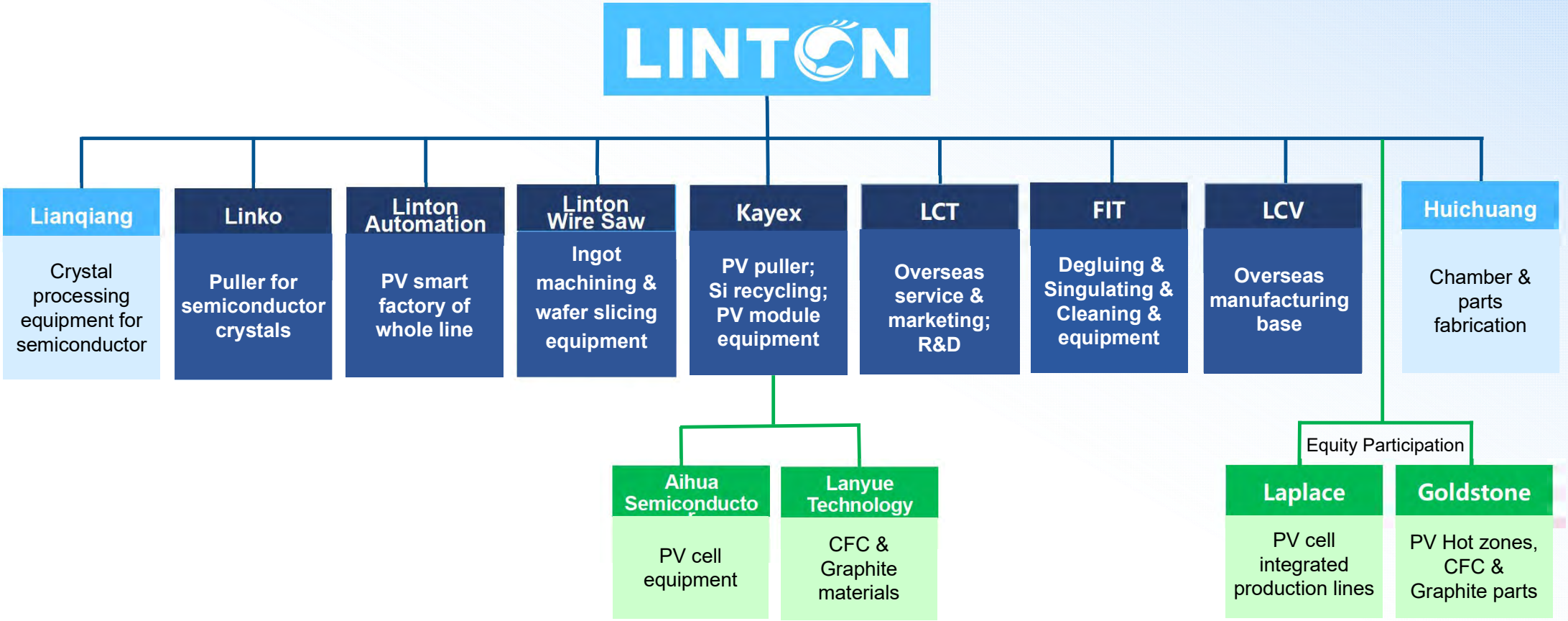
3 Wholly-Owned Subsidiaries

23 Holding Subsidiaries

6 Affiliated Companies

Guided by “Reliable, Value-Adding, and Sunshine,” Linton is committed to adding value to every solution to our customers and empowering the future of global clean energy and semiconductor technology.

GROUP STRUCTURE & PRODUCT PORTFOLIO



R&D AND MANUFACTURING BASES

Dalian R&D and Manufacturing Base

- **Wafer slicers**
- **Cropper, Squarer, Grinder**
- **Automation and smart factory solution**
- Si microwave crushing equipment;
- Si, SiC, Sapphire slicing equipment;

Wuxi R&D and Manufacturing Base

- **Pullers for PV Crystal growth;**
- Puller for semiconductor crystals;
- Ge,Gallium oxide, sapphire crystal growing equipment
- SiC crystal growers & synthesizers
- Si wafer cleaning, PV cells & module equipment

US Sevice R&D Base

- **70+ years of puller design & manufacturing experience (via Kayex);**
- Advanced R&D of crystal growth;
- **Service & Support to US customers (from Rochester NY)**

Vietnam Manufacturing Base

Overseas manufacturing base

- Monocrystal furnace
- Wafer slicer
- Ingot machining equipment
- Other equipment

Wuxi Base	Dalian Base	Ingot Puller Output	Slicer & Machining output	Equal to
180,000+	100,000+	1200+	500+	200+GW
Square Meters	Square Meters	Unit/Month	Unit/Month	Annual Capacity

GROWTH PATH

Path of Linton Technologies Group

2007

Founded on September 25th.

2008

Developed **1st PV wire saw (squarer)** in China.

2012

Developed **1st PV diamond wire slicer**.

2013

Acquired KAYEX (Est. in 1952). From SPX of USA.

Became the global leader of Pullers for crystal growth.

Quantity delivery of DW slicers.

2014

Quantity delivery of ingot machining equipment: **grinders croppers, etc.**

GROWTH PATH

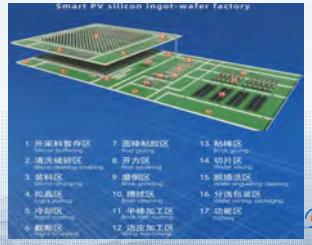
Path of Linton Technologies Group

2017

Developed **world's 1st 1600 model crystal puller,** setting standard for PV crystal growth.

2019

Developed **1st** ingot & wafer automation line for PV industury.



2020

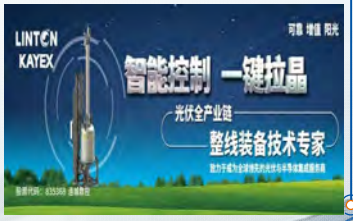
Listed on **Beijing Stock Exchange**.

2021

Developed **world's 1st 1700 model crystal puller,** leading the trend of PV crystal growth. Starting quantity delivery of SiC furnaces.

2023

Developed **AI based "One-click Crystal Pulling"** for KX380PV & KX520PV platforms.



2024

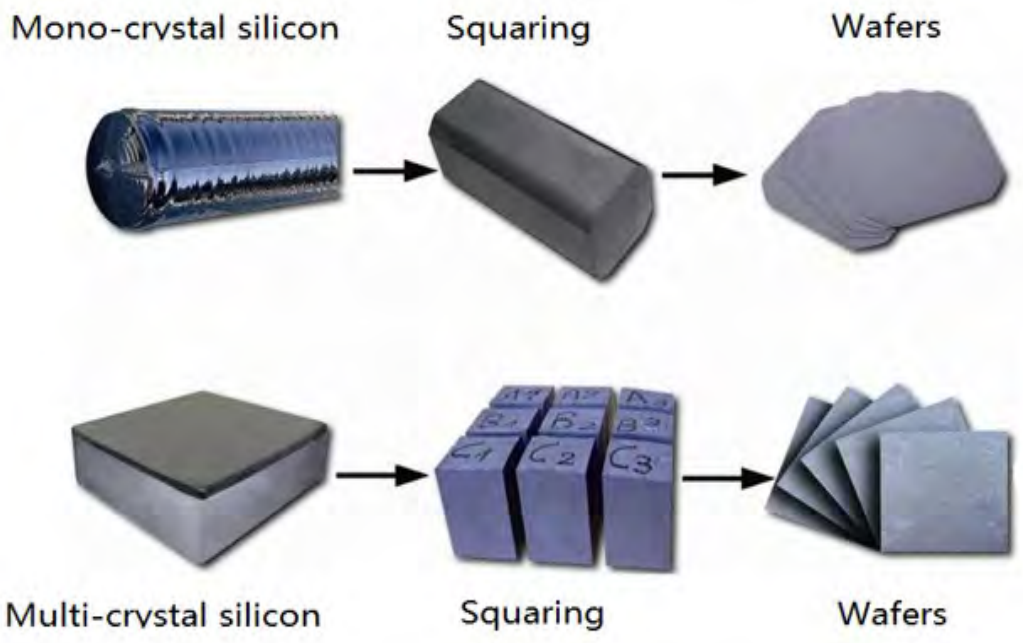
Established Linton crystal Vietnam.

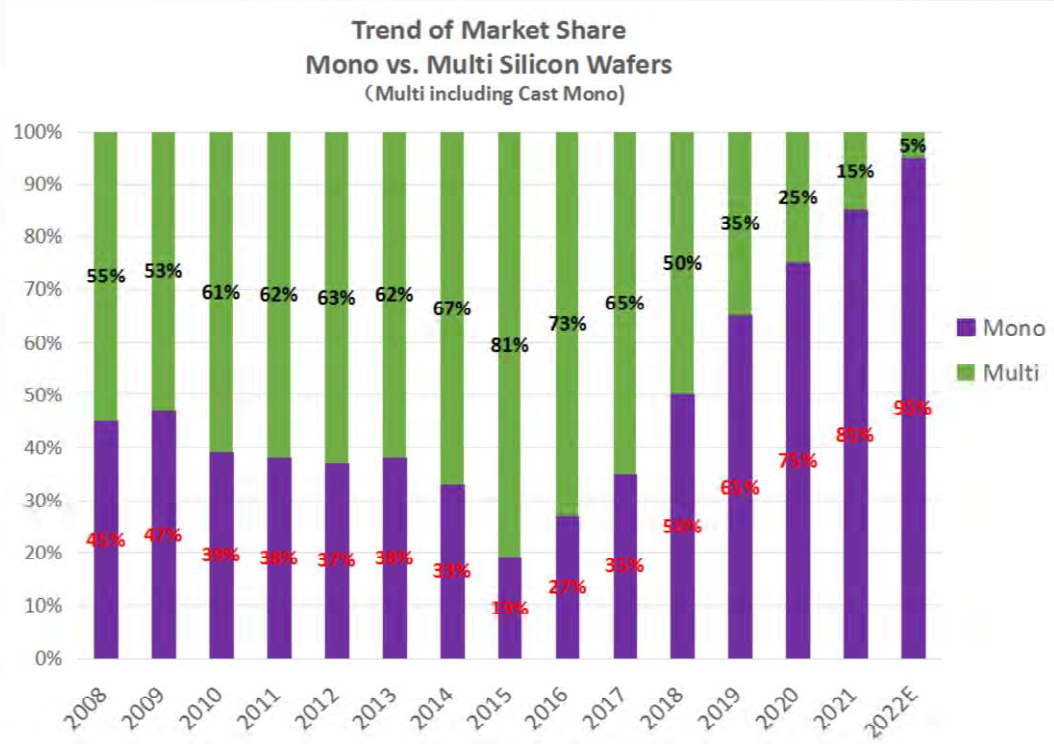
Developed newer generation 1800 model crystal puller.

TECHNICAL LEADERSHIP OF LINTON - 1

LINTON

Linton promoted mono-crystal technology while most companies in PV industry believed in multi-crystal technology. Linton finally reshaped the PV industry together with our partners.



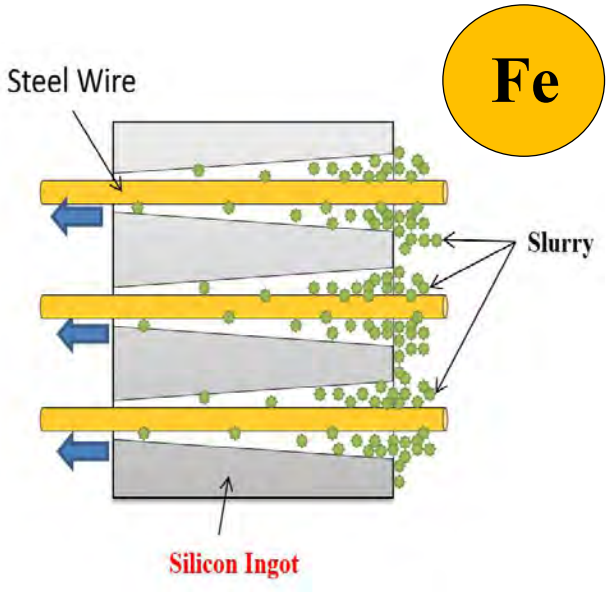


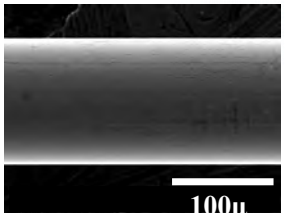
TECHNICAL LEADERSHIP OF LINTON - 2

LINTON

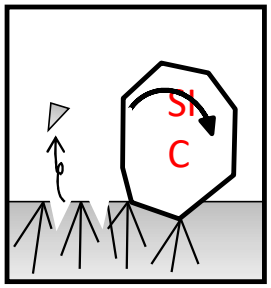
Linton promoted diamond wire slicing technology while most companies in PV industry believed in slurry slicing technology. Linton again reshaped the PV industry together with our partners.

Slurry Slicing

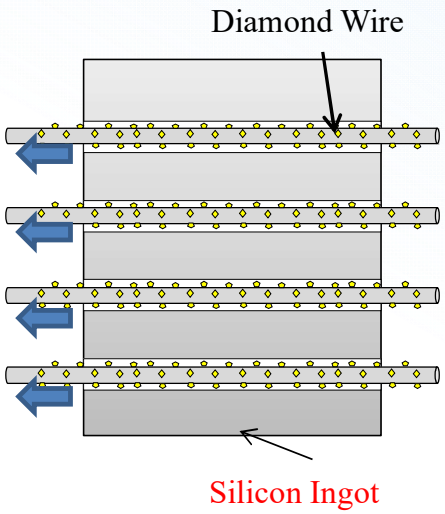


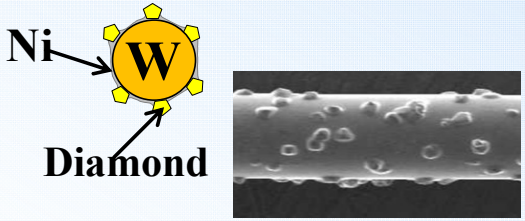


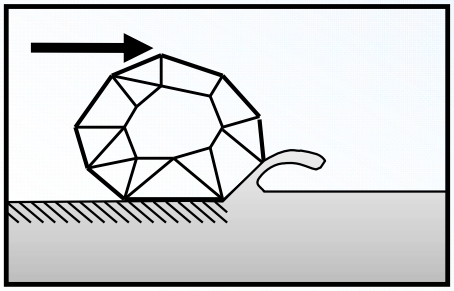
+SiC Slurry



DW Slicing



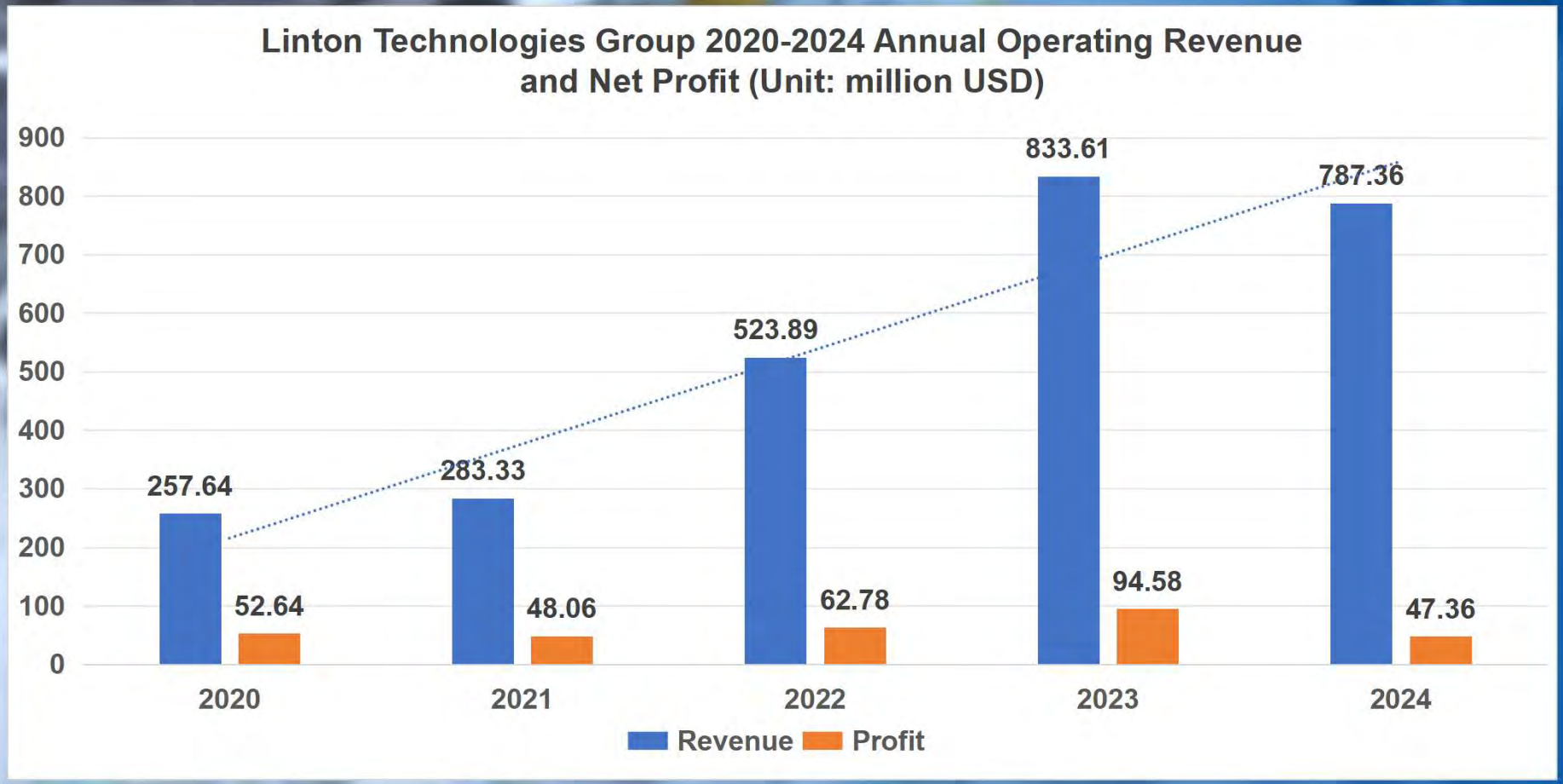




20+ times increase in productivity

REVENUE AND PROFIT

Sustained Growth



PRODUCTION CAPACITY

Reliable Project Execution

500+ GW

in total delivery

150+ GW

peak annual delivery

SHIPMENT VOLUME OF CORE PRODUCTS

Steady Sales Market Leadership

As of 2025

20000+ unit
Monocrystal furnance Global Shipment Volume

40+%
Market share (approx.)

10000+ unit
Wafer Slicers & Ingot Processing Machines Global Shipment Volume

35+%
Market share (approx.)

» Monocrystal Pullers

» Wafer Slicing Machines

GLOBAL PRESENCE

Linton has service teams in the **USA**, Vietnam, Singapore, Europe, India, Turkey, and Malaysia, with businesses spanning 20+ countries and regions worldwide.

Client Distribution/ Service Center

- South Korea
- Japan
- Vietnam
- Singapore
- Russia
- Malaysia
- Taiwan, China
- Kazakhstan
- Kyrgyzstan
- **India**

R&D Center

- Dalian
- Wuxi
- Vietnam
- Rochester, USA

TECHNOLOGY LEADERSHIP

Delivering long-term customer value through sustained technological innovation

Technological innovation

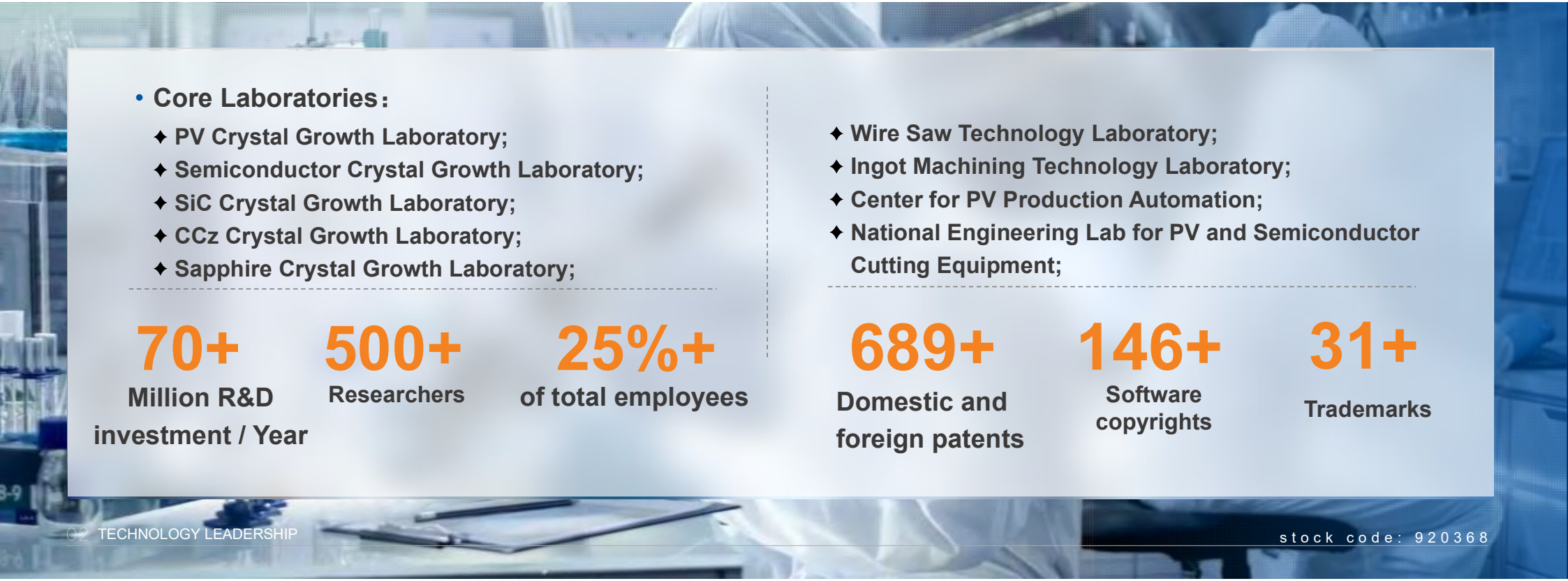
Driving the advancement of the PV and semiconductor equipment industries

stock code:920368

ADVANCED TECHNOLOGY

R&D and Intellectual Property Rights

Experts from all around the world cooperated with top level universities and academia, together built a R&D system with global competitiveness.



- **Core Laboratories：**
  - ✦ PV Crystal Growth Laboratory;
  - ✦ Semiconductor Crystal Growth Laboratory;
  - ✦ SiC Crystal Growth Laboratory;
  - ✦ CCz Crystal Growth Laboratory;
  - ✦ Sapphire Crystal Growth Laboratory;
  - ✦ Wire Saw Technology Laboratory;
  - ✦ Ingot Machining Technology Laboratory;
  - ✦ Center for PV Production Automation;
  - ✦ National Engineering Lab for PV and Semiconductor Cutting Equipment;

70+ Million R&D investment / Year

500+ Researchers

25%+ of total employees

689+ Domestic and foreign patents

146+ Software copyrights

31+ Trademarks

SCIENTIFIC RESEARCH STRENGTH

LINTON

Technology Support Through University Enterprise Cooperation

Joint Linton-Academia Research Center with the Chinese Academy of Science.

4 National Scientists

4 SEMI Standards Directors, State Honored Experts

2 University-Enterprise Joint R&D Centers

PULLER

Type	Model	Chamber (mm)	Throat (mm)	Receiving chamber (mm)	Seed Lift load (Kg)	Crucible Lift Load (Kg)	Total equipment weight	Crucible charge weight	Crucible diameter				
									33 in.	37 in.	40 in.	42 in.	44 in.
1600+	KX380PV	⌀ 1600*2050	⌀ 410	⌀ 410*5500	1500	2000	≈16 tons	Total charge	700kg	1000kg	1150kg	/	/
1700	KX520PV	⌀ 1700*2100	⌀ 450	⌀ 450*5500	1500	2000	≈17 tons		700kg	1000kg	1150kg	1300kg	/

Type	Delivery	Hot zone compatibility	Compatibility	Product description	Standard Configuration	Optional Configuration
1600+	The 1st in the industry to develop and deliver **over 8,000 units** in Qty.	Standard 37 in. Max 40 in.	Compatible with 1700 equipment factory layout.	Meets the demand for larger charging capacity and larger crystal growth, with multiple modules reserved for cost-effective upgrades. The 1700 model meets the growth requirements of 16-inch crystals.	1.One-click crystal pulling 2.Centralized control sys. 3.Low oxygen crystal pull 4.High-efficiency heating power supply 5.High-speed vacuum pump 6.High-efficiency filtration tank;	1.Data center & big data analysis 2.Vision server 3.Production MES system 4.Low Oxygen crystal pulling 5.Extension chamber 6.CCz process equipment 7.MCz/MCCz magnetic field 8.High-efficiency hot zone 9.Production auxiliary tools
1700	The 1st in the industry to develop and deliver **over 3,000 units** in Qty.	Standard 37/40 in. Max 42 in.	Compatible with 1600+ equipment factory layout.			

Technological Leadership:

1.Equipped with the next-generation digital intelligence platform, **daily output greatly increased, leading the industry.**

2.Power consumption reduced by more than 10%, leading the industry.

3.Reduced water usage, with cooling water flow as low as 30m³/h.

4.Multiple oxygen control solutions and configurations available, as low as 6PPM, ensuring more uniform resistivity and longer minority carrier lifetime.

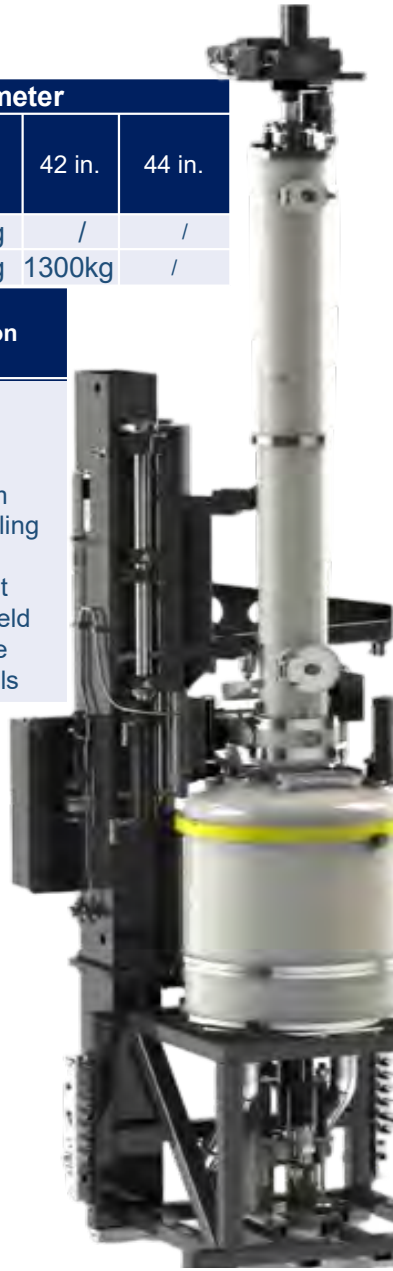
5.Maximum hot zone size of 42 inches, compatible with CCz and magnetic fields.

Intelligent Crystal Pulling:

1.Integration of BI and AI based on equipment big data to optimize the entire process flow.

2.Intelligent control system with one-click crystal pulling & full process automation, automatically recommending pulling power and necking-shouldering profile with accuracy rate of ≥99%.

3.AI-based visual inspection and automatic crucible placing modules with improved accuracy, stability, and safety.



THE 6TH GENERATION WAFER SLICER

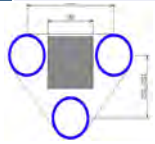
LINTON

Wafer Spec.	Shaft Distance	Linton	Competitor/ A	Competitor/ B	Competitor/ C
182&210 half wafer	Horizontal	280mm	315mm	310mm	325mm
	Vertical	245mm	260mm	245mm	255mm
182 wafer & 182*210 rectangular wafer	Horizontal	350mm	360mm	360mm	375mm
	Vertical	220/240mm	230mm	220/240mm	230mm
210*210 wafer	Horizontal	379mm	390mm	395mm	410mm
	Vertical	250mm	260mm	250mm	273mm
230*230 wafer	Horizontal	400mm	415mm	410mm	425mm
	Vertical	265mm	280mm	265mm	255mm

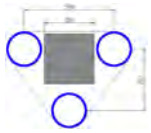
Space Requirement	
QP950	4700mm×2100mm×3350mm
Competitor A	3980mm×3100mm×3200mm
Competitor B	5435mm×2430mm×3430mm
Competitor B	4778mm×2168mm×3257mm

QP950

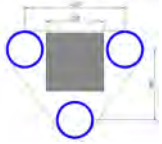
280 shaft distance: 105x210mm/ 91x182mm



350 shaft distance: 182x182mm/ 182x210mm



379 shaft distance: 210x210mm



400 shaft distance: 230x230mm

1. Optimized and adjustable wheelbase for cutting wafers of different specifications.
2. Supports full & half-brick formats, flexible configurations accommodate all wafer specifications.
3. Small wheelbase: 350mm for 182×182mm wafers and 379mm for 210×210mm wafers.
4. Up to 1200mm brick length (Optional).

Performance

- Brick Length: Max 1000mm×1PCS (standard length 950mm)
- Brick Size: 182 & 210 full & half wafer, ~230 wafer compatible
- Slicing Structure: 3-shaft structure
- DW wire running speed: Max 45m/s
- Horizontal adjustable distance: 280~400mm
- Vertical adjustable distance: 221~280mm
- Main roll diameter & length: 3-Max Φ150mm*1060mm
- Electrical system: Inovance customized system
- Automatic loading mode: front/rear loading & unloading (optional)
- Slurry tank volume: Max 800L

Specification

- Average TTV ≤10 μm; Average saw mark value ≤10 μm, A product rate ≥97%
- 19 different shaft pitch is fully compatible with 182-230 specifications for square, rectangular and half wafers
- **Thickness of silicon wafer can be ≤55μm**
- **Automatic feeding centering, automatic centering of wings**
- **Automatic detection of wire jump, bow, cut through**
- **Automatic cleaning of machine chamber, automatic cleaning fluied tank and pipes**
- Reduce cycle time by 20min

02 TURNKEY SOLUTION

Transition from equipment maker to solution provider.

COOPERATIVE PARTNERS

Served 10+ leading enterprises

Delivered 60+ automatic factory projects

Linton provides 1 station service for setting up integrated ingot & wafer production lines

Customers in PV industry

Trinasolar | 高佳太阳能 | JA SOLAR | MeiKeEnergy | 中环 ZHONGHUAN
SUNREV 新奥飞能科 | JinKO Solar | 隆基 | ET Solar | INDOSOL
阿特斯 | 华耀 HUA YAO | 晶品 | 通威集团 | AUO
南玻集团 | LONGi | SST GROUP | YUZE 宇泽半导体 | Reliance Industries Limited
高景太阳能 Gokin Solar | 东方希望 EAST HOPE | SUNGROW | NORWEGIAN CRYSTALS | SANY
协鑫 GCL | HONSUN 鸿新新能源 | NORSUN | Hanwha Q CELLS | 横店东磁

Customer for PV Turnkey Solution

LONGi | Hanwha Q CELLS | 华耀 HUA YAO | ET Solar
INDOSOL | Reliance Industries Limited | 晶品 | 阿特斯

The largest project: Erdos Inner Mongolia

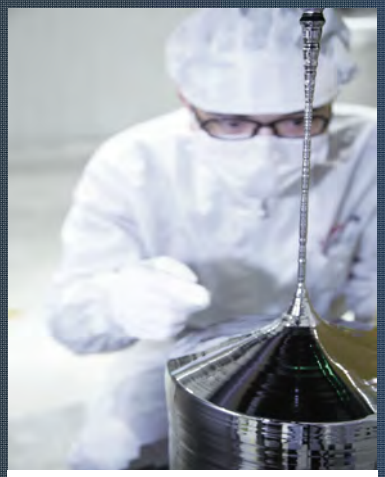
60+GW

PROJECT EXPERIENCE

Overseas Project Highlights

South East Asia Project L

Scale: **10** GW
Delivery: 2023
Location: Malaysia



North America Project Q

Scale: **3.3** GW
Delivery: 2025
Location: US

European Project A

Scale: **2** GW
Delivery: 2023
Location: Europe

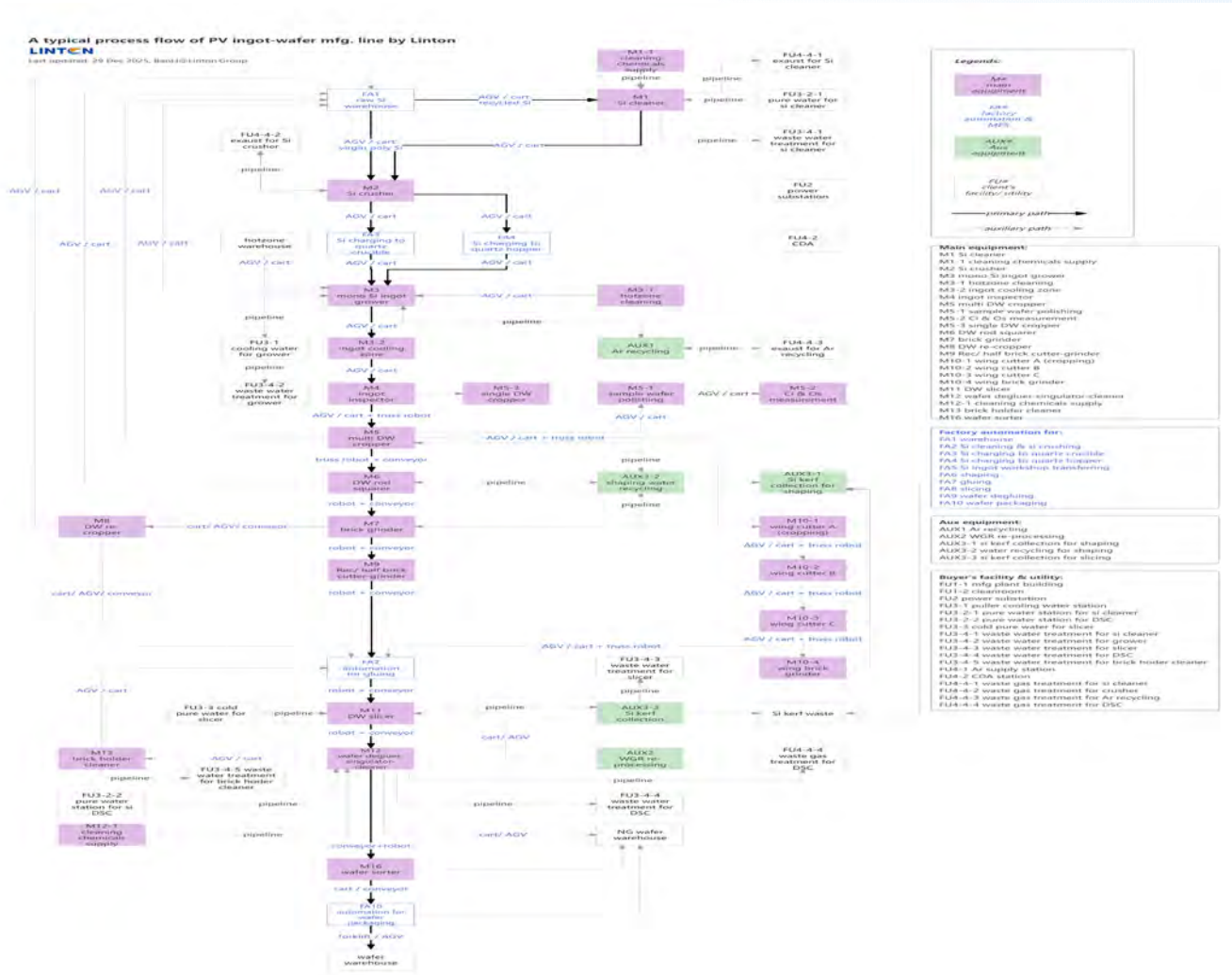
South Asia Project B

Scale: **12** GW
Delivery: 2025
Location: India

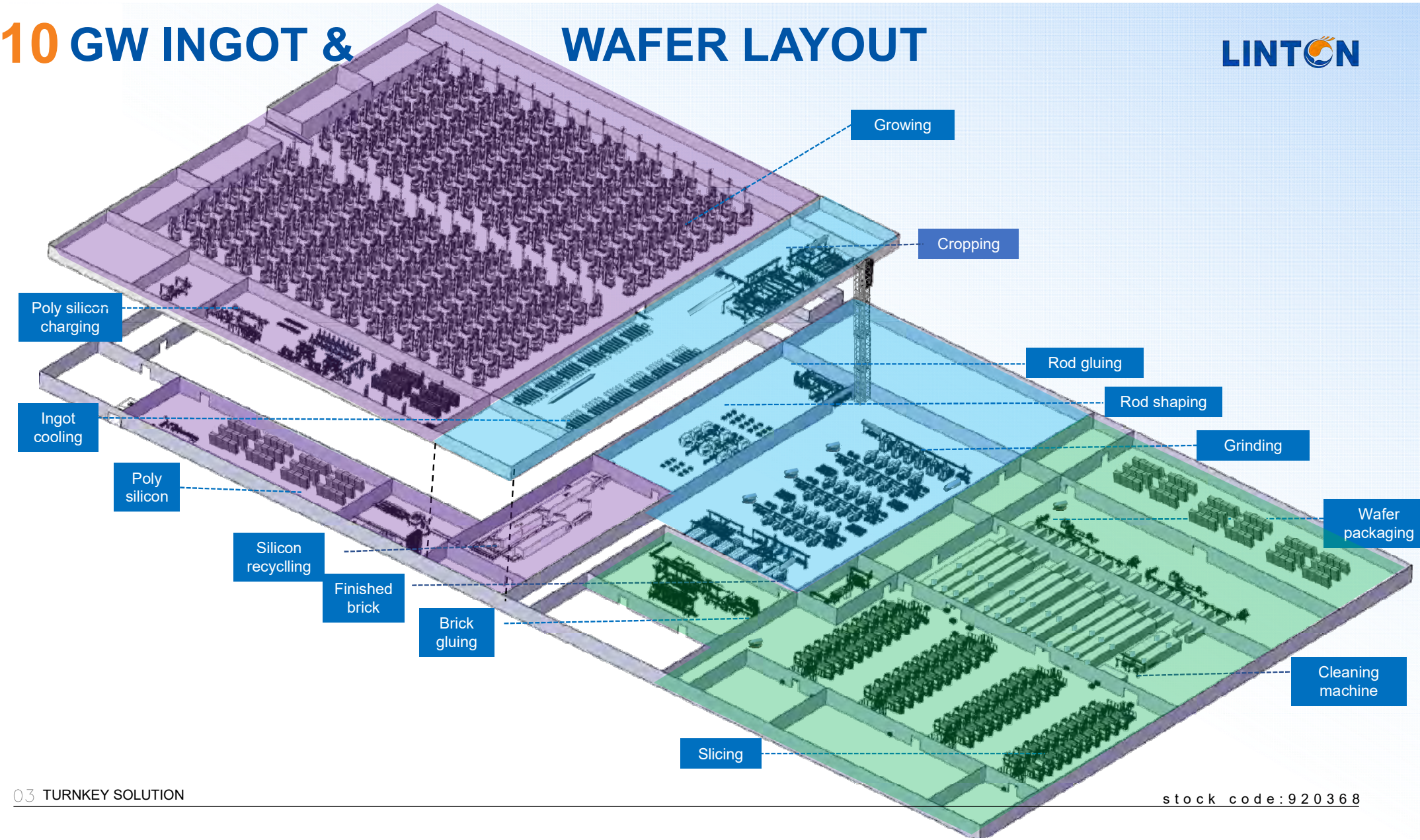
South East Asia Project E

Scale: **3** GW
Delivery: 2025
Location: Vietnam

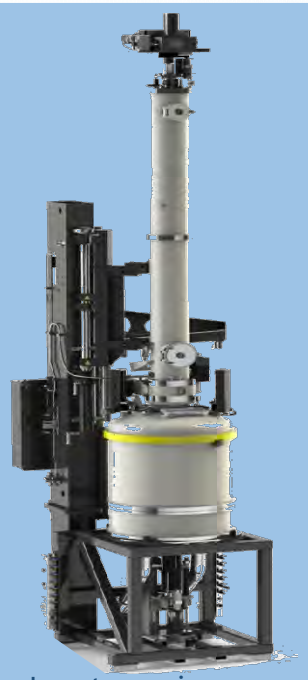
PV INGOT & WAFER PROCESS FLOW



10 GW INGOT & WAFER LAYOUT



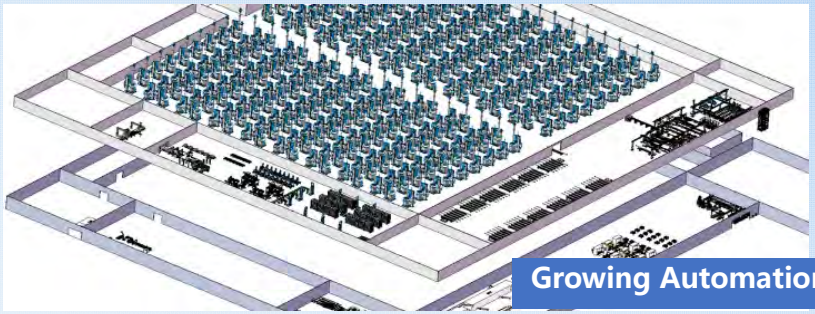
10 GW INGOT & WAFER SMART FACTORY SOLUTION LINTON



Ingot growing

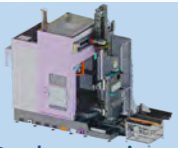
Silicon crushing

Silicon cleaning



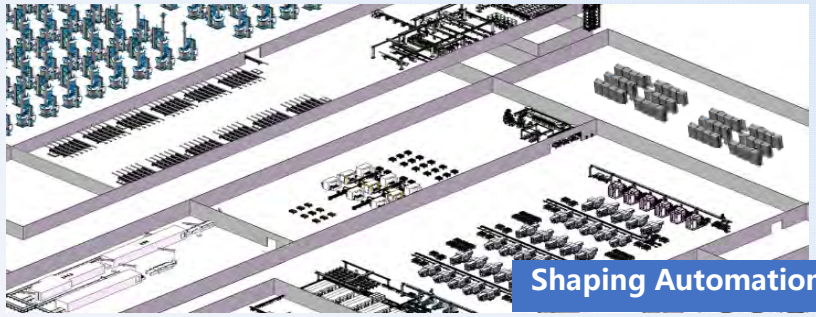
Growing Automation

Ingot cropping



Rod squaring

Brick grinding

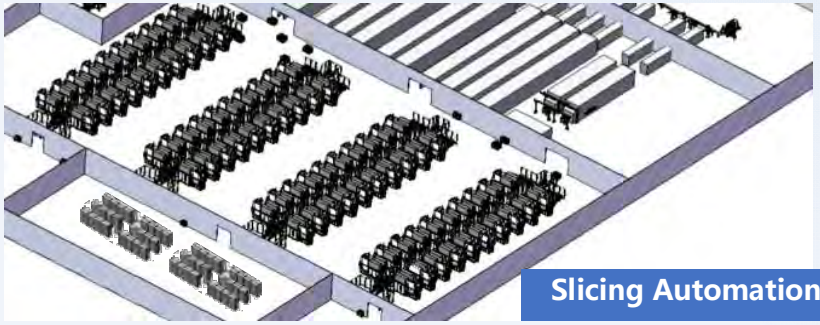


Shaping Automation

Wafer slicing

Wafer degluing

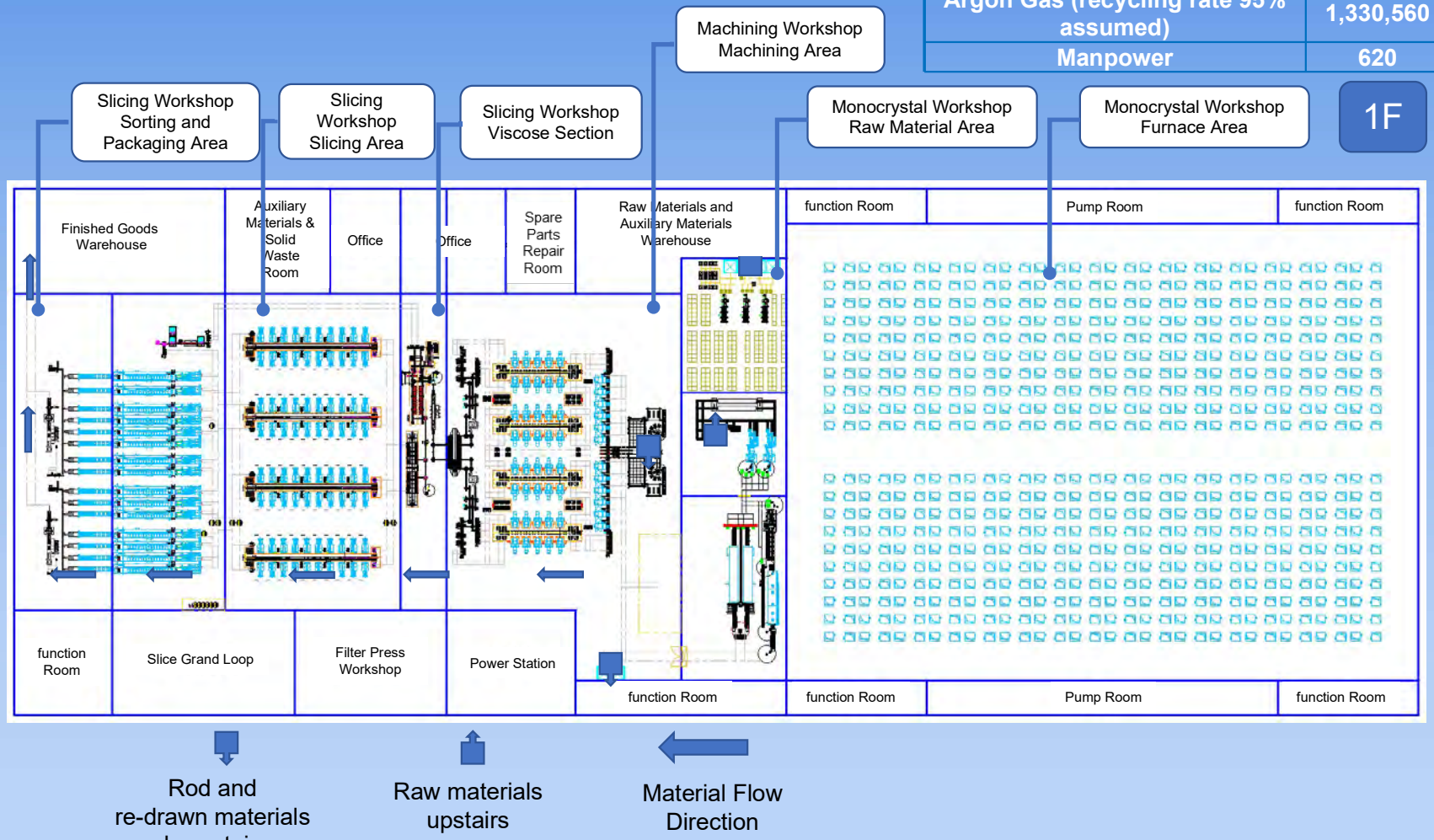
Final cleaning



Slicing Automation

10 GW INGOT & WAFER LAYOUT

Total Power	75,000	KW
Total Power (consumption)	505,000,000	KWh/Year
Water (consumption)	1,980,000	CBM/Year
Workshop Area	92000	㎡
Argon Gas (recycling rate 95% assumed)	1,330,560	CBM/Year
Manpower	620	Pers.



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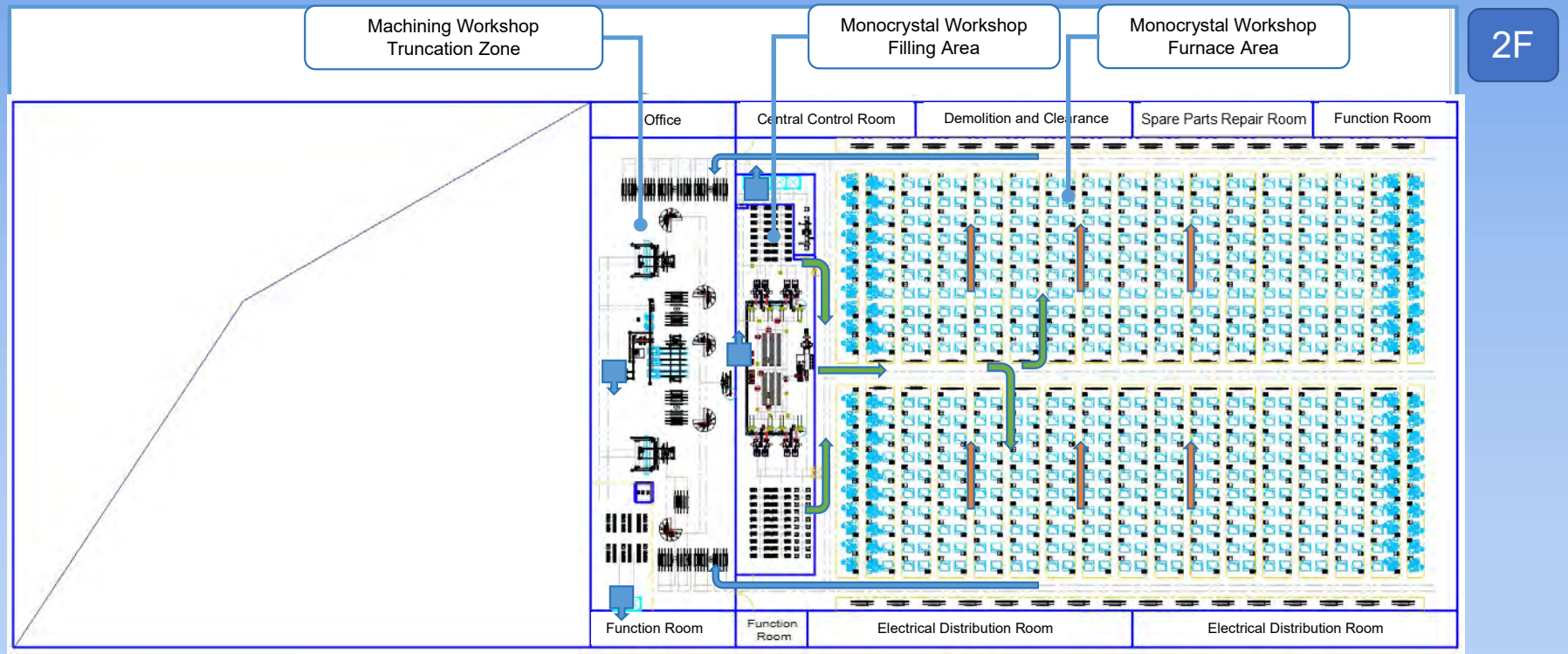


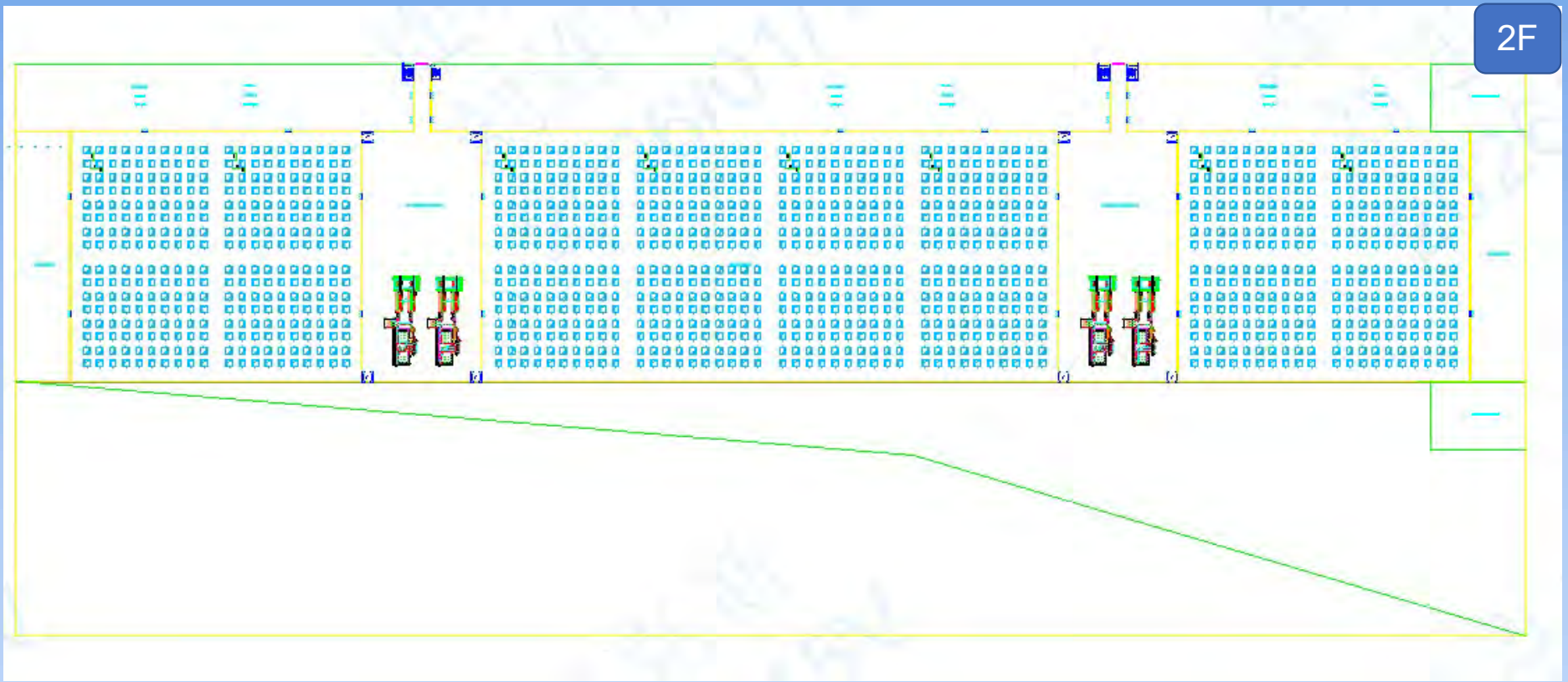
20 GW INGOT & WAFER LAYOUT

Total Power	150,000	KW
Total Power (consumption)	1,098,000,000	KWh/Year
Water (consumption)	3,960,000	CBM/Year
Workshop Area	186,300	㎡
Argon Gas (recycling rate 95% assumed)	2,661,120	CBM/Year
Manpower	1,180	Pers.

1F

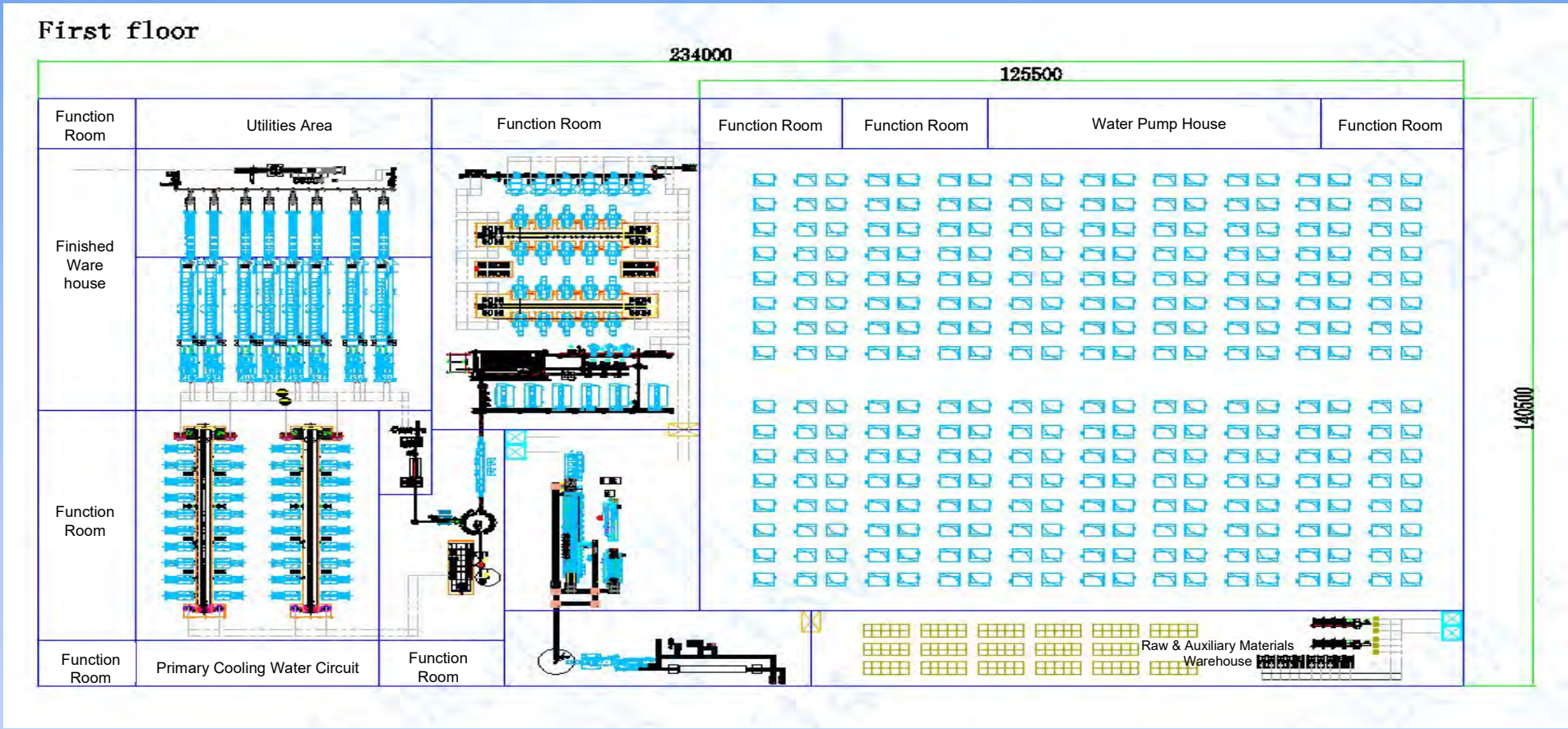
20 GW INGOT & WAFER LAYOUT

Total Power	150,000	KW
Total Power (consumption)	1,098,000,000	KWh/Year
Water (consumption)	3,960,000	CBM/Year
Workshop Area	186,300	㎡
Argon Gas (recycling rate 95% assumed)	2,661,120	CBM/Year
Manpower	1,180	Pers.



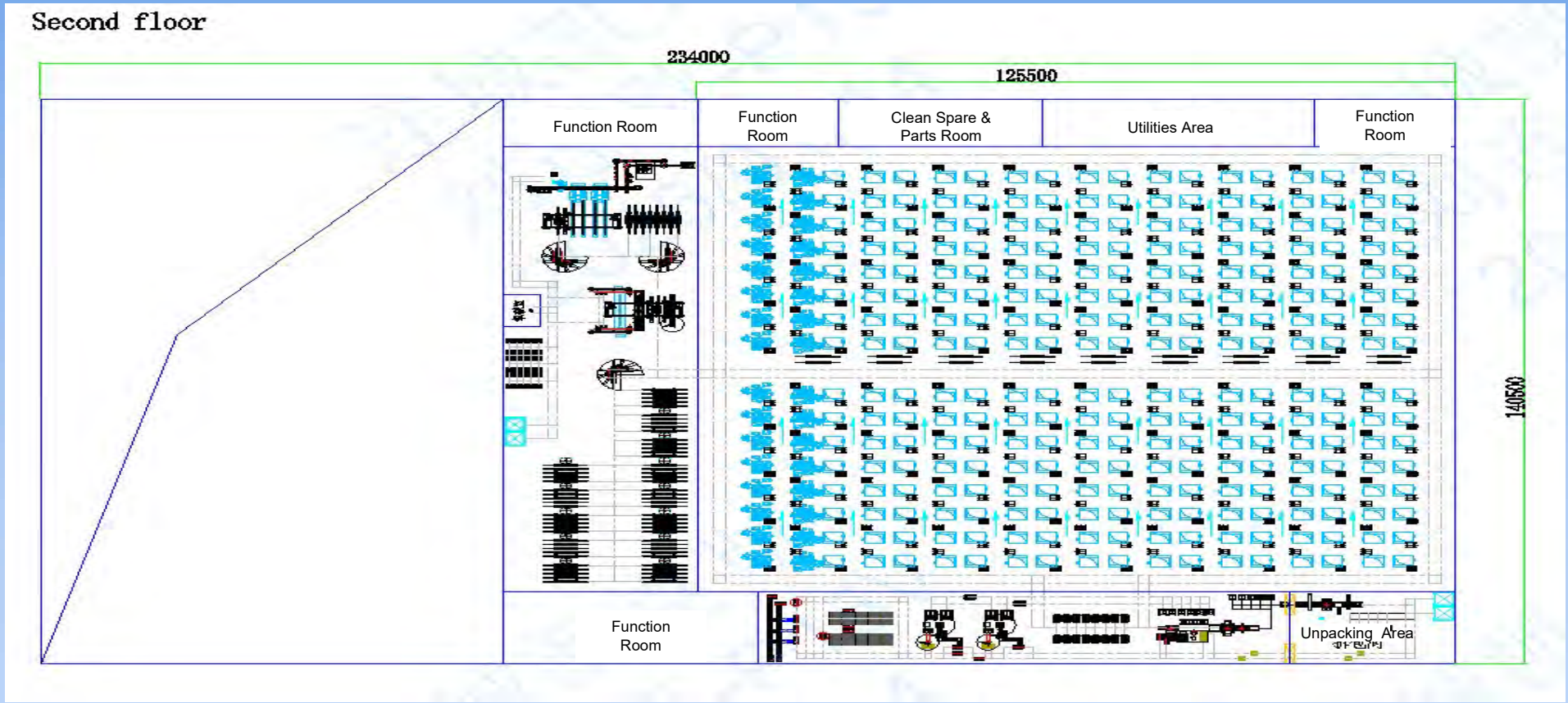
5 GW INGOT & WAFER LAYOUT

Total Power	37,500	KW
Total Power (consumption)	253,000,000	KWh/Year
Water (consumption)	990,000	CBM/Year
Workshop Area	45,200	㎡
Argon Gas (recycling rate 95% assumed)	665,280	CBM/Year
Manpower	360	Pers.



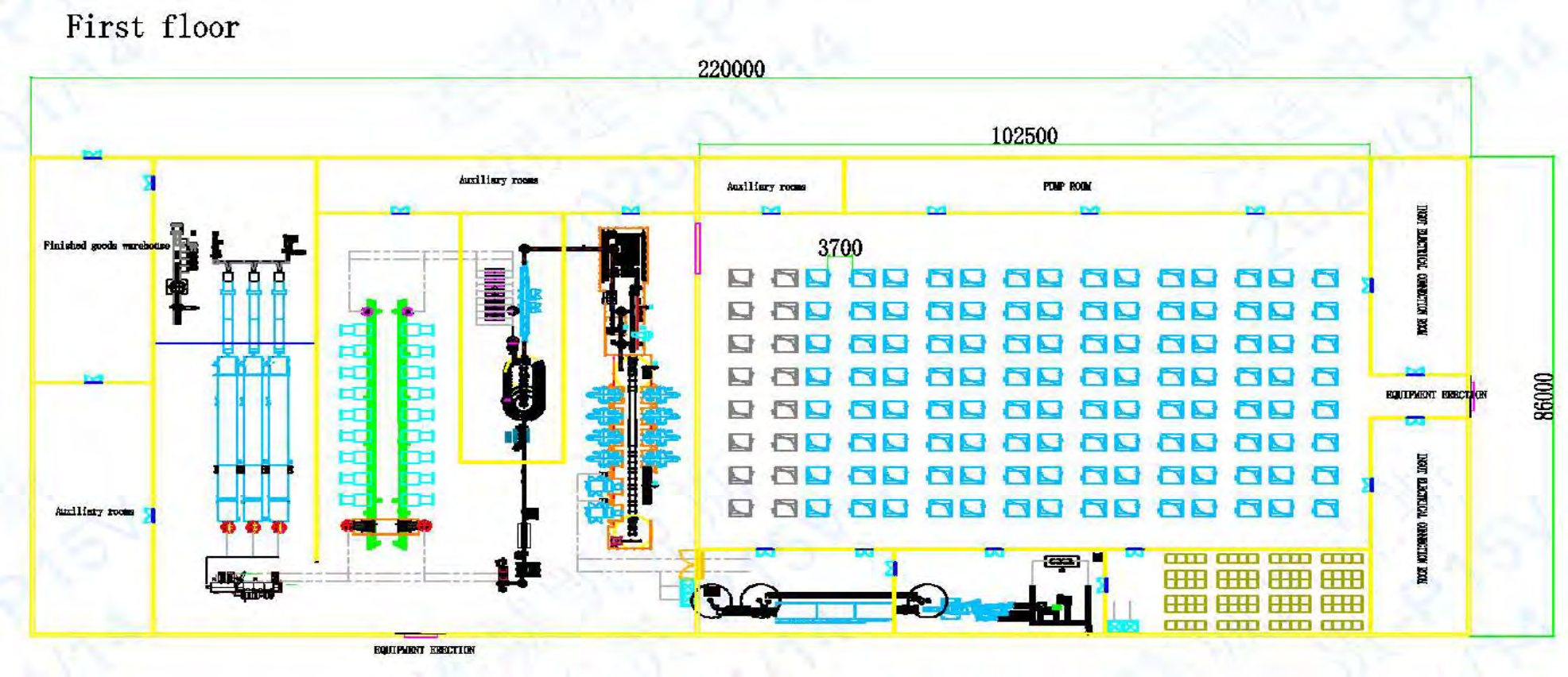
5 GW INGOT & WAFER LAYOUT

Total Power	37,500	KW
Total Power (consumption)	253,000,000	KWh/Year
Water (consumption)	990,000	CBM/Year
Workshop Area	45,200	㎡
Argon Gas (recycling rate 95% assumed)	665,280	CBM/Year
Manpower	360	Pers.



2 GW INGOT & WAFER LAYOUT

Total Power	15,000	KW
Total Power (consumption)	103,900,000	KWh/Year
Water (consumption)	396,000	CBM/Year
Workshop Area	18,920	㎡
Argon Gas (recycling rate 95% assumed)	266,112	CBM/Year
Manpower	180	Pers.



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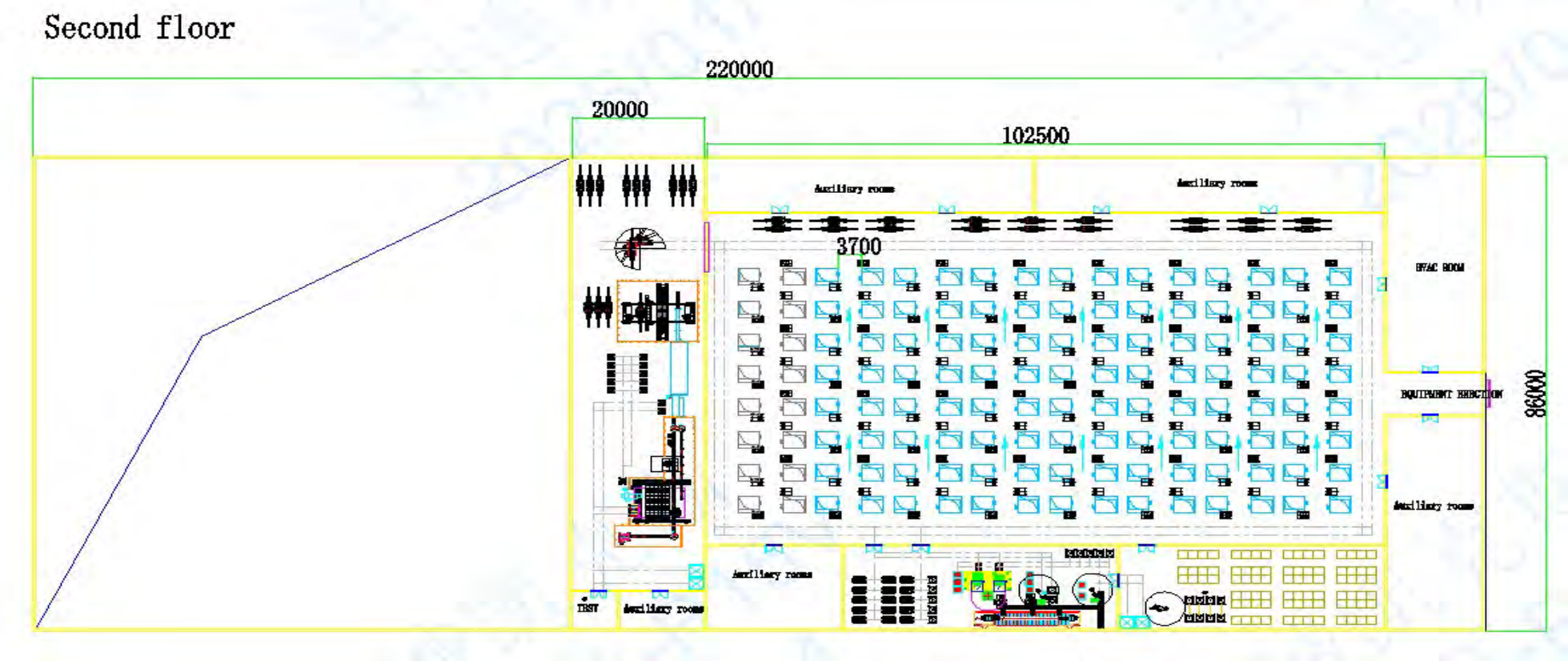
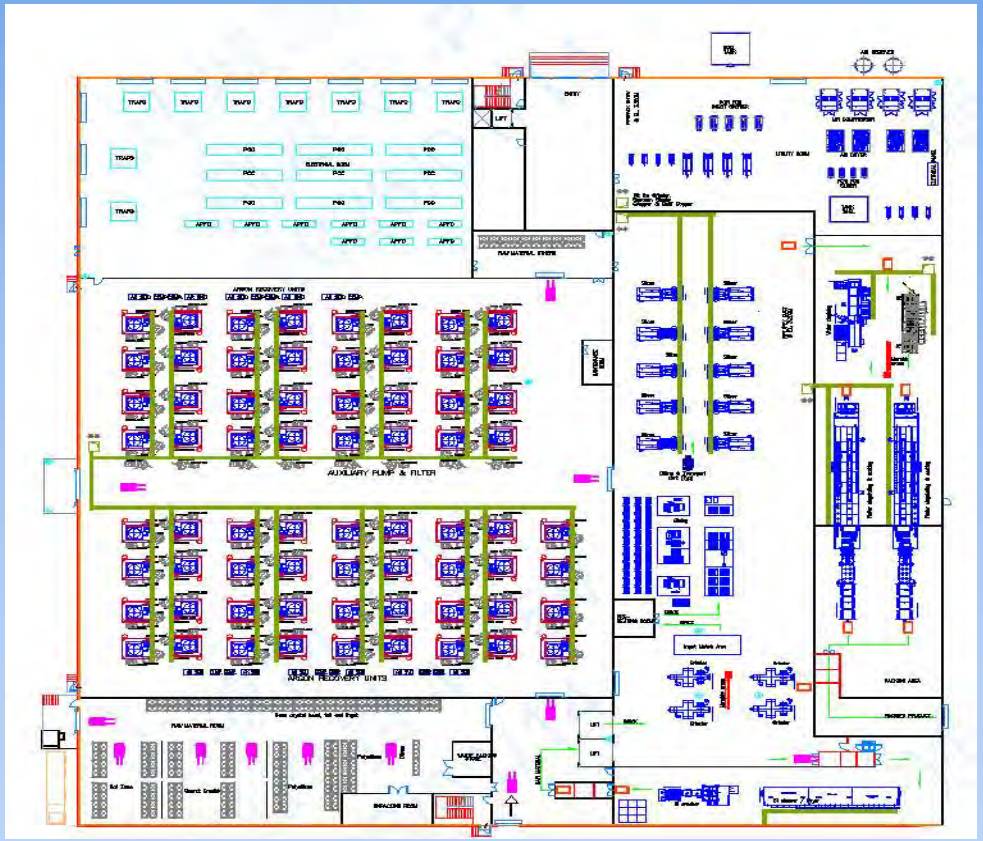
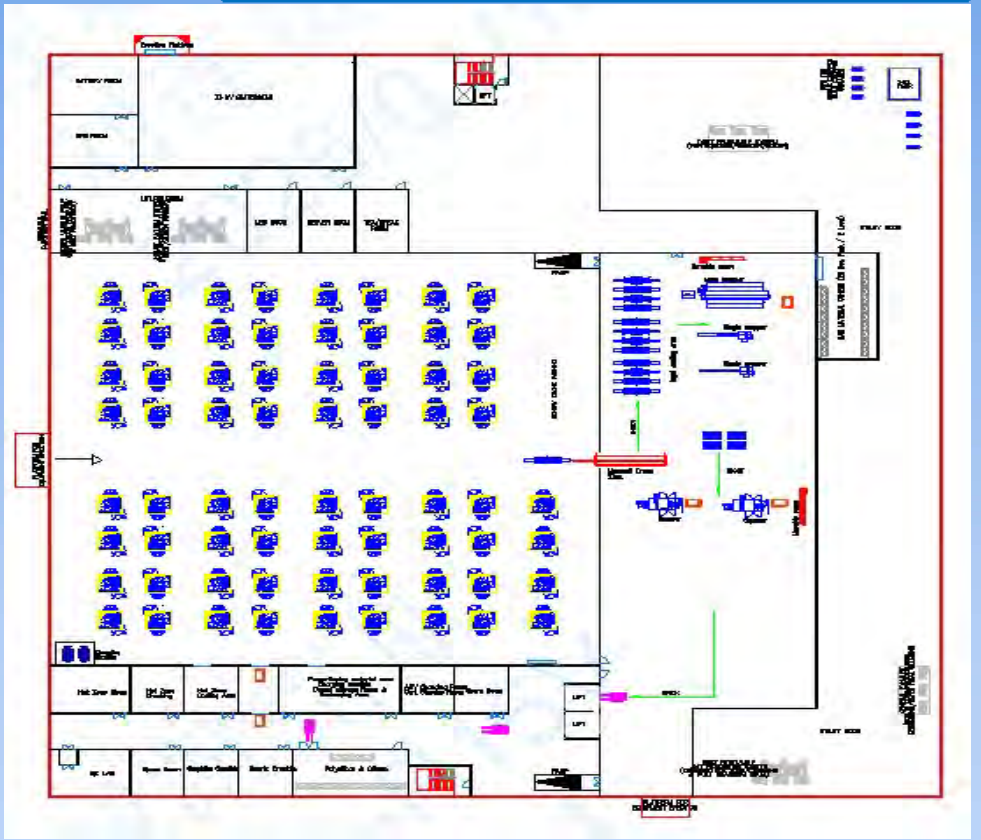


1 GW INGOT & WAFER LAYOUT

Total Power	7,800	KW
Total Power (consumption)	52,700,000	KWh/Year
Water (consumption)	198,000	CBM/Year
Workshop Area	11,800	㎡
Argon Gas (recycling rate 95% assumed)	133,056	CBM/Year
Manpower	105	Pers.



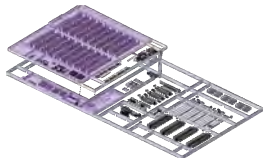


INGOT & WAFER TURNKEY SOLUTION

LINTON

Intelligent Manufacturing + Digitalization+AI Big Data

GROWING AUTOMATION



GROWING AUTOMATION - CORE MODULES

Material box turnover

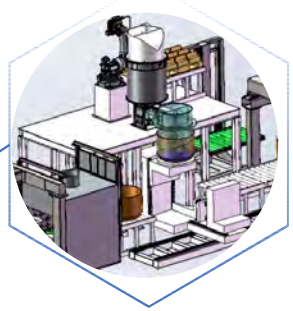
Auto crusher connection (loading / weighing) & AGV / roller conveyor transfer

Smart warehouse

Auto formula management, precise feeding per charging plan

Hopper charging

Auto tilt-charging for hoppers, metal isolation design to prevent contamination



Crucible charging

Auto crucible rotation-charging & Metal isolation anti-contamination

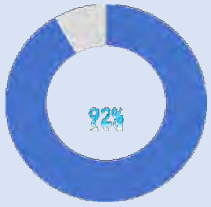
Puller area AGVs

Automatic transfer of Puller area materials

Automatic crystal extraction

Automatic crystal extraction & Multi-rod length compatibility

Automation Rate



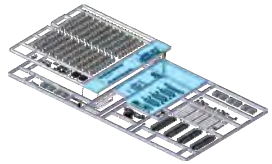
Automation Rate

- Crushing / cleaning, intelligent material preparation, charging & transfer modules form a fully automated growing workshop production line

Automation Rate

- Modular design for customer needs
- Integrates puller central control, builds crystal growth shop smart manufacturing system with auto material management & AGV transport

SHAPING AUTOMATION



SHAPING AUTOMATION - CORE MODULES

Ingot inspection

Ingot length / diameter / facet line inspection, with laser coding. Optional hidden crack detection system

Electrical testing

Automatic ingot resistivity testing, 6-axis robot for increased accuracy & flexibility

Ingot gluing

Integrated ingot rotation for facet line alignment, fully automated rod adhesive bonding

Automatic loading and unloading

Auto loading /unloading for cropping, squaring, grinding & recropping

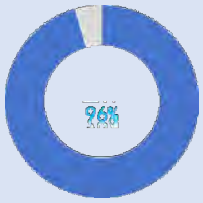
Brick inspection

Auto brick inspection (size / angle / perpendicularity), optional chipping & hidden crack detection

Brick stacking and packaging

Fully automated stacking & packaging of finished square bricks

Automation Rate



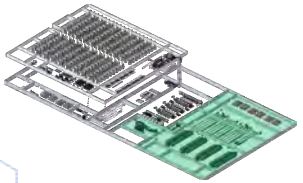
Performance

- Shaping automation with multi-module integration for a fully automated shaping workshop

Performance

- Modular design for customer needs
- Integrated control, scheduling & MES enable ingot-to-brick auto-digital-intelligent processing, lower labor requirement, higher production efficiency

GLUING AUTOMATION



AUTOMATIC GLUING LINE - CORE MODULES

Microwave heating of Si bricks

Bricks are heated to the optimum process temperature by microwave heating, so that the glue can adhere better and improve quality of gluing

Brick destacking & feeding

Automatic destacking of bricks and packaging materials for brick feeding operation

Brick Inspection and rolling-over

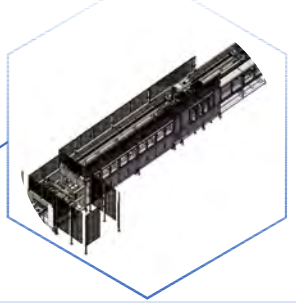
Inspect perpendicularity and edge chipping of brick end face, automatically turn and match the surfaces for optimized brick gluing results

Positioning & pre-curing warehouse

Use three-in-one positioning & curing warehouse to ensure accurate positioning of bricks in the pre-curing process

Finished product cache

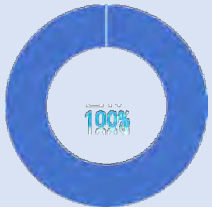
Data system of incoming bricks linked with MES of slicing workshop, realizing the management of storage, waiting time and specification recording of the finished products



Brick holder degluing & cleaning

Brick holder automatic loading, unloading, degluing & cleaning, automatically connecting with brick gluing line

Automation Rate



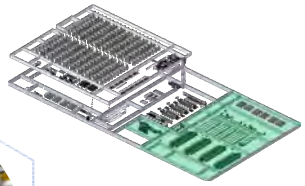
Performance

- Brick depalletizing, inspection and turning, microwave heating, automatic brick pairing, resin plate cleaning, brick holder degluing & cleaning, brick pre-curing, finished product testing & storage, constitute the automatic gluing line

Performance

- Unique three-in-one positioning & curing process closely links each process steps and realizes multi product gluing with higher curing accuracy
- Automatic gluing process eliminates manual intervention, enhancing production efficiency and product quality

SLICING AUTOMATION



SLICING AUTOMATION - CORE MODULES

Discharging from warehouse, sorting and transferring

Automatic brick pairing for glue line, high efficiency material distribution per wafer slicing plan

Automatic loading & unloading of slicer

Automatic material distribution per wafer slicing plan, automatic slicer loading/unloading

Unloading mechanism

Auto degluing rack positioning & sliced brick pickup, AGV docking for empty/full degluing rack exchange

Material separation and transfer after slicing

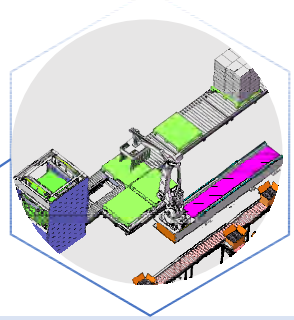
AGV realizes empty/full degluing rack turnover, automaticly connecting wafer slicers & degluing units

Reinspect & packaging of wafer

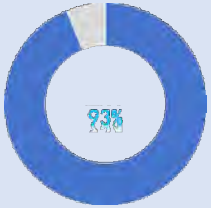
A-grade wafer reinspection & packaging, automatic wafer packaging with box opening & sealing

Finished product palletizing and packing

Automatic transfer of boxed wafers, palletizing & wrapping after packing



Automation Rate



Performance

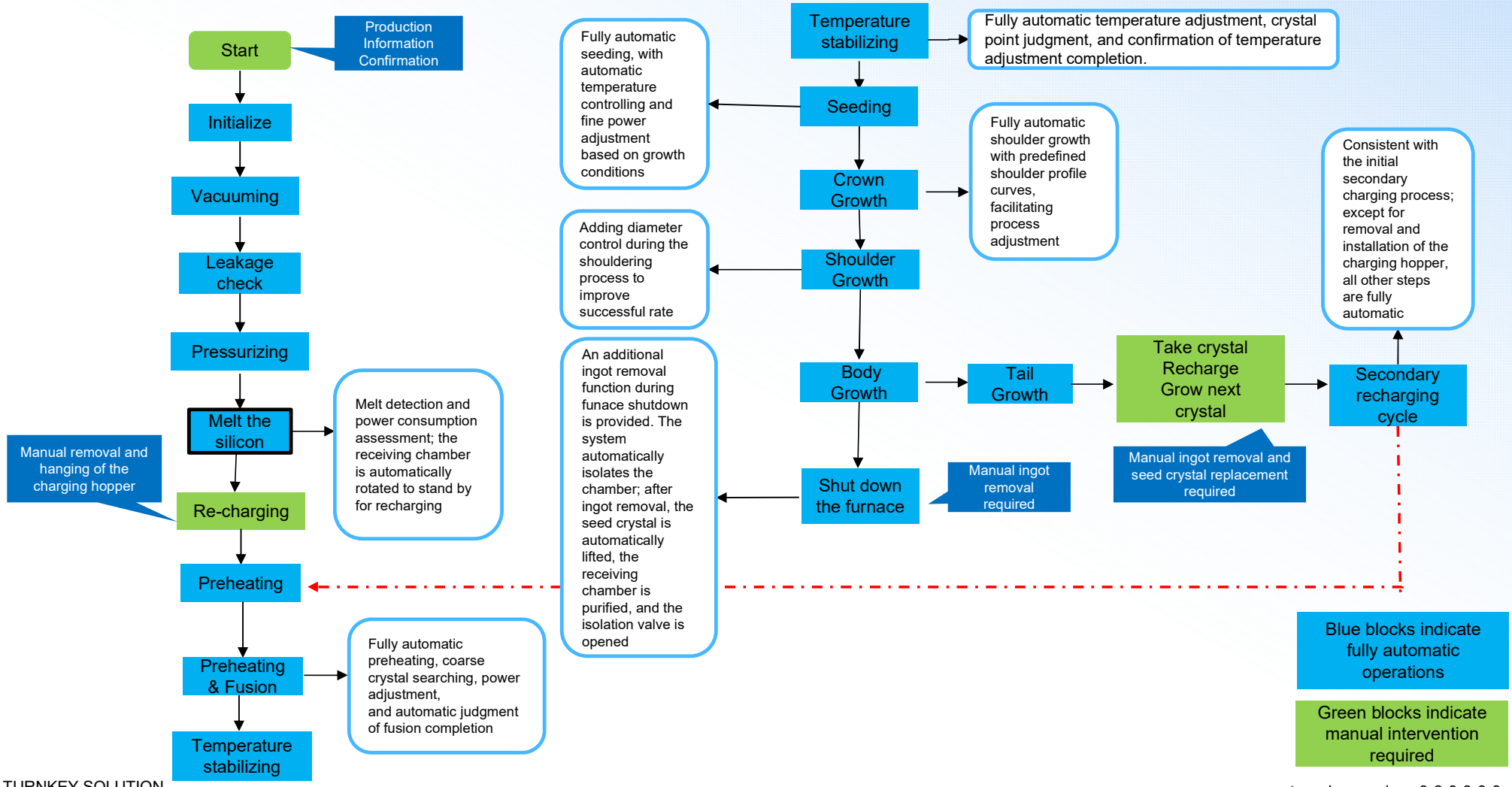
- Automatic slicing workshop with multi-modules forming an intelligent wafer production line

Performance

- Modular design for customer needs.
- Smart manufacturing system for wafer slicing workshop with intelligent scheduling, brick pairing, automatic slicing systems, degluing machine, wafer sorting & packaging line

ONE-CLICK CRYSTAL PULLING PROCESS

LINTON



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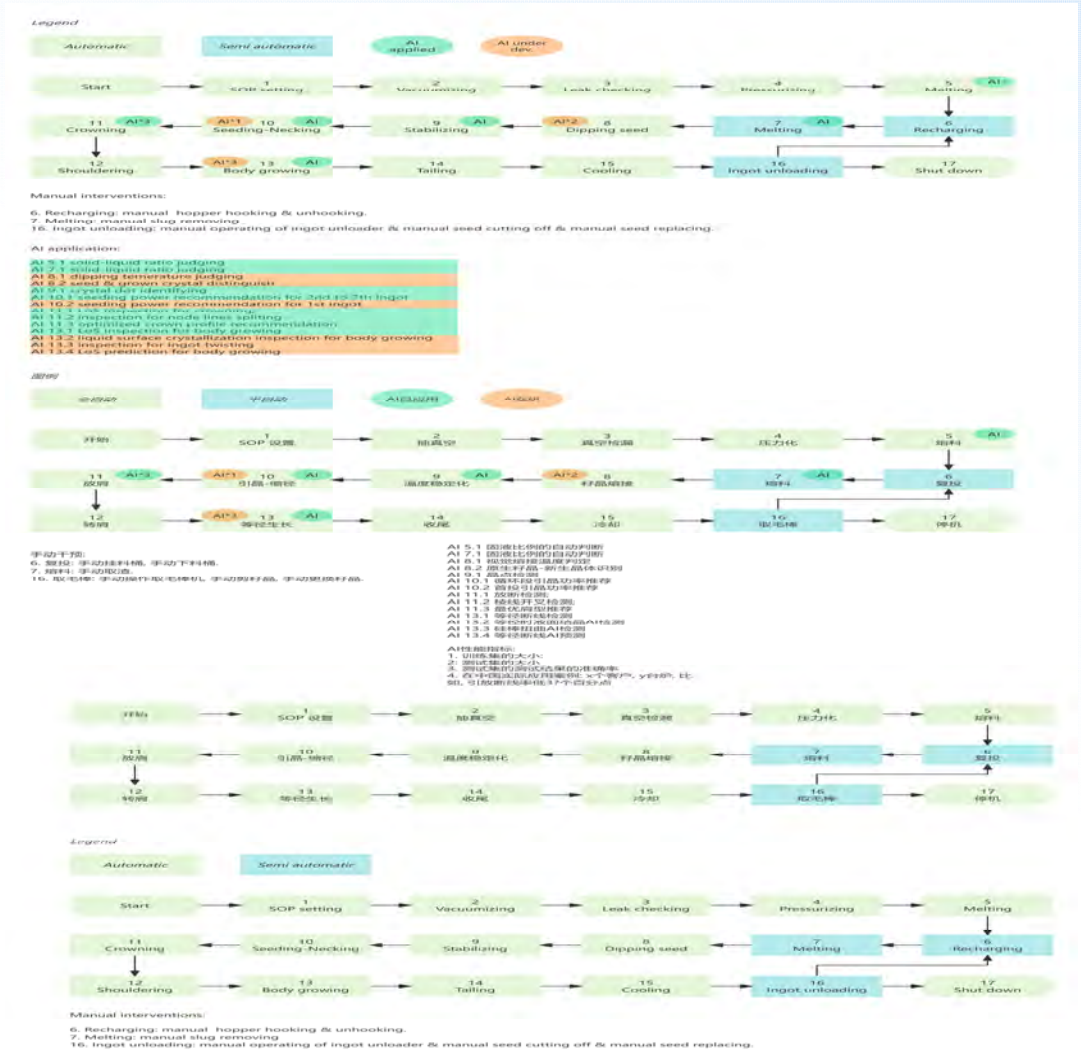


AI & MES Integration

LINTON

Process Positioning & Alignment Assistance

Output:
Centerline & Boundary & Deviation

Action:
Overlay alignment guide lines Out-of-tolerance alarm

Example Indicator:
Positioning accuracy ≤1mm

Quantity Recognition & Automatic Update

Output:
Quantity Missing & Extra & Blocked piece alert

Action:
Auto-update indicators
Review task trigger

Value:
Reduce manual counting
Decrease errors

Automated Quality Control

Output:
Defect identification & Classification

Action:
Intercept & handle
Generate traceability report

Value:
Improve consistency
Reduce labor cost

Closed-Loop Delivery & System Integration

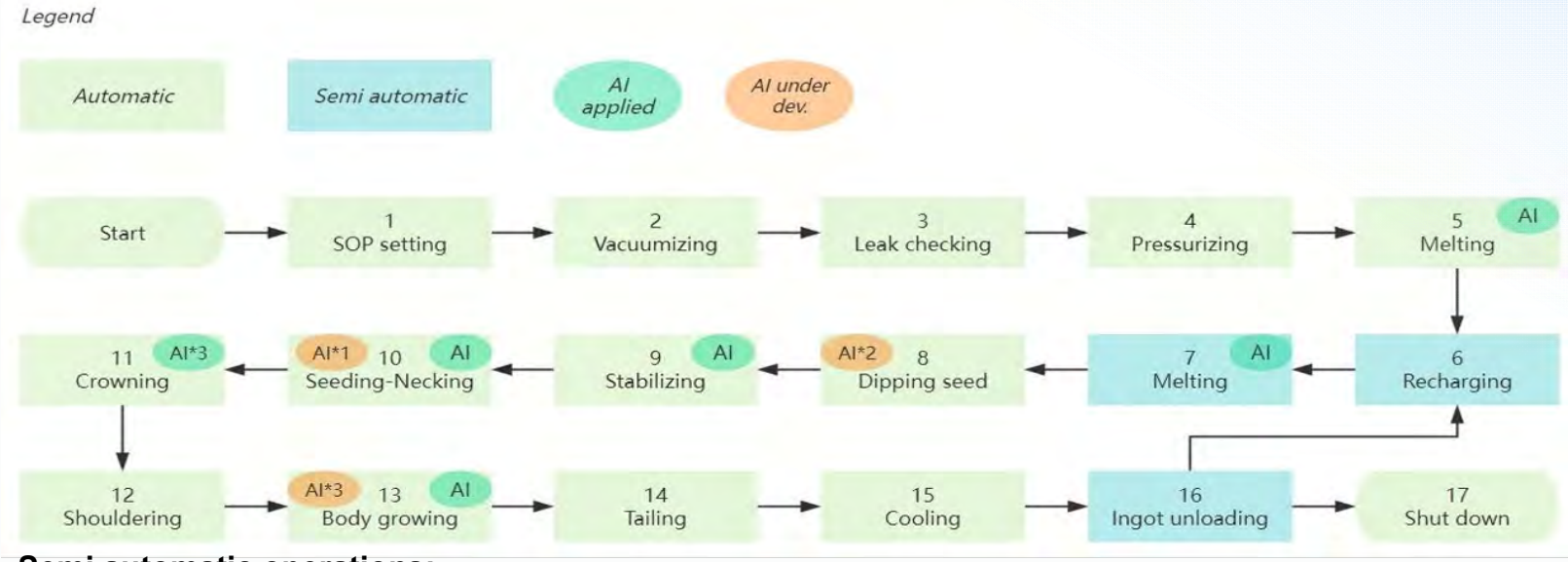
Input:
Camera & Sensor & Equipment data collection

Integration:
API service
Database write-back

Execution:
Work order & traceability
Closed-loop operation

Visual/Sensor Data → AI Service → MES Write-back (Work Order/Traceability) → Closed-Loop Optimization

FULL-PROCESS AI & BI APPLICATION POINTS



Semi automatic operations:

6. Recharging: manual hopper hooking & unhooking.

7. Melting: manual slug removing

16. Ingot unloading: manual operating of ingot unloader & manual seed cutting off & manual seed replacing.

AI applications:

AI 5.1 solid-liquid ratio judging
AI 7.1 solid-liquid ratio judging
AI 8.1 dipping temerature judging
AI 8.2 seed & grown crystal distinguish
AI 9.1 crystal facet dot identifying
AI 10.1 seeding power recommendation for 2nd to 7th ingot
AI 10.2 seeding power recommendation for 1st ingot
AI 11.1 LoS inspection for crowning;
AI 11.2 inspection for node lines spliting
AI 11.3 optimized crown profile recommendation
AI 13.1 LoS inspection for body growing
AI 13.2 liquid surface crystallization inspection for body growing
AI 13.3 inspection for ingot twisting
AI 13.4 LoS prediction for body growing

QUALITY ASSURANCE

High-level Products & High-quality Services

Large Quantity Delivery Capability

1

Supports customer scaling and rapid capacity expansion with industry-leading efficiency.

"121" Service Objectives

2

1 hour inquiry response.
2 working days for a customized solution.
1 calendar week for product return/exchange

R&D Capability

3

Enables customers to achieve advanced production capacity through core technologies and smart factories.

Solutions

4

Provides customers with turnkey smart solutions for photovoltaic silicon wafering.

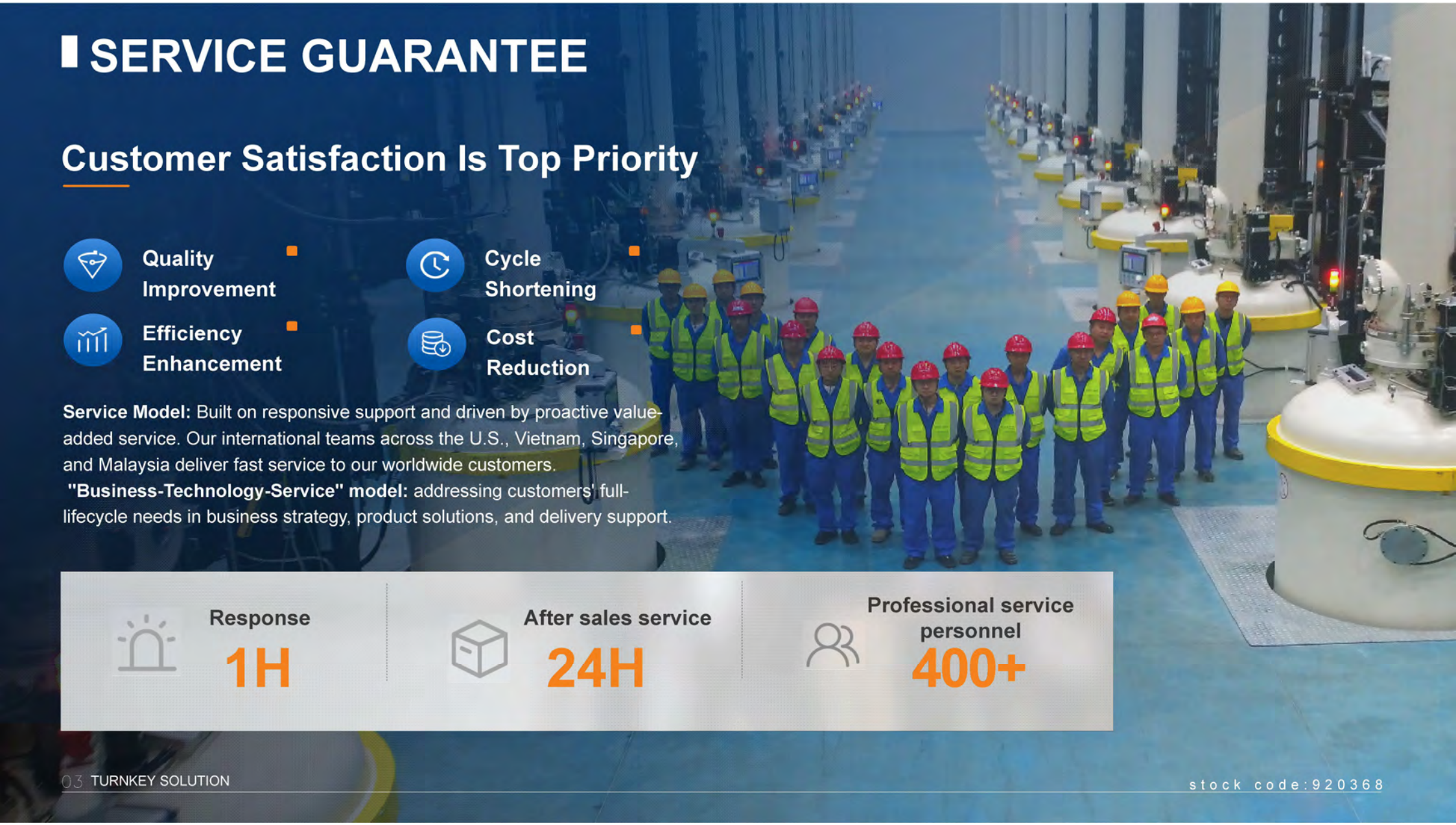
SERVICE GUARANTEE

Customer Satisfaction Is Top Priority

- **Quality Improvement**
- **Cycle Shortening**
- **Efficiency Enhancement**
- **Cost Reduction**

Service Model: Built on responsive support and driven by proactive value-added service. Our international teams across the U.S., Vietnam, Singapore, and Malaysia deliver fast service to our worldwide customers.

"Business-Technology-Service" model: addressing customers' full-lifecycle needs in business strategy, product solutions, and delivery support.



Response	After sales service	Professional service personnel
1H	24H	400+

CROPPER & RE-CROPPER

Multi wire cropper

QDHD35700

LINTON

Performance

- Ingot Diameter: Ø240 ~ 350mm
- Ingot length: Max7200mm
- Cropping speed: 0~100mm/min
- Wire speed: 0 ~ 50m/s
- Loop wire diameter: 0.42 ~ 0.65mm
- Outer size of machine (main): 19670x3100x3200mm
- Rated power: 50kW
- Weight: 32t

Specification

- Improved ingot support structure, edge chipping ≤1mm, end perpendicularity ≤0.5mm
- It can be mounted in dual-wire configuration, and the **output per unit is ≥3.5GW**
- Automatic wire breakage recognition
- Equipped with automatic facet line detection and alignment function

Sinlge loop wire re-cropper

QDHA35100

Performance

- Ingot Diameter: Ø240 ~ 350mm
- Ingot Length: 2-980mm
- Cropping speed: ≥50mm/min
- Wire speed: 0 ~ 50m/s
- Loop wire diameter: 0.42 ~ 0.65mm
- Outer size of machine (main): 3100*1900*2700mm
- Rated power: 5kW
- Weight: 3t

Specification

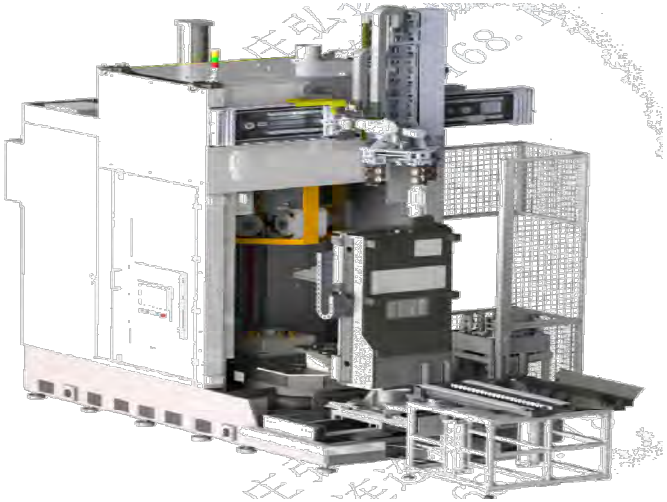
- Automate the re-cropping process by connecting the workpiece with the servo feeding table
- High efficiency and stability, optional double wire double servo tension configuration, to achieve one-time cutting of sample wafers
- Algorithm update, optimize tension control, feed process, improve the quality of finished products
- **Loop wire life ≥120 cuts**
- The daily capacity is 100+ cuts

SQUARER & GRINDER

4-Loop Wire Squarer

QHFA2395

LINTON



Performance

- Wafer side length: 180-235mm
- Ingot length: 200-950mm
- Squaring speed : 0~80mm/min
- Wire speed: 0 ~ 70m/s
- Loop wire diameter: 0.42~0.65mm
- Squaring time: ≤15min/cut
- Outer size of machine (main): 5410*2450*4580mm
- Rated power: 41kW
- Weight: 12t

Specification

- Higher productivity，with superior capacity of 1 GW/Set
- Equipped with rotary exchaing table, preparation time ≤30s
- 4 loop wires cut at the same time with tension control algorithm, with variation ≤0.15mm
- 1200mm ingot length optional

Grinder

LT-GMSR2510

Performance

- Wafer side length: 166-235mm （compatible with half brick: 182x91 210x105)
- Ingot length: 200-1050mm
- Cycle time: ≤35min/pcs (M10/830mm)
- Dimension accuracy: ≤±0.03mm
- Roughness: Ra≤0.1μm
- Grinding wheel spec: 250-320mm
- Outer size of machine: (main) 5410*2960*2400mm
- Rated power: 61kW
- Weight: 12t

Specification

- Automatic feeding and centering, intelligent positioning of the workpiece, improved compatibility to abnormal bricks
- Automatic detection of dimensional margin, intelligent matching of cutting depth, improved processing efficiency
- Automatic detection of tool wear with intelligent compensation, improved accuracy of finished product
- Automatic 5-D feeding table enables **0.1mm margin grinding**
- **"High speed, large cutting depth, fast feed", daily output of square bricks ≥4.2 tons**
- 1200mm ingot length optional

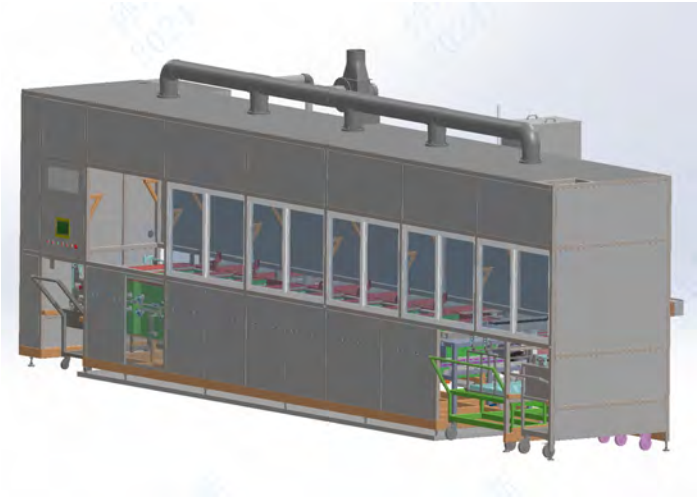
stock code:920368

DEGLUING, SINGULATING & CLEANING MACHINE

LINTON

Wafer degluing machine

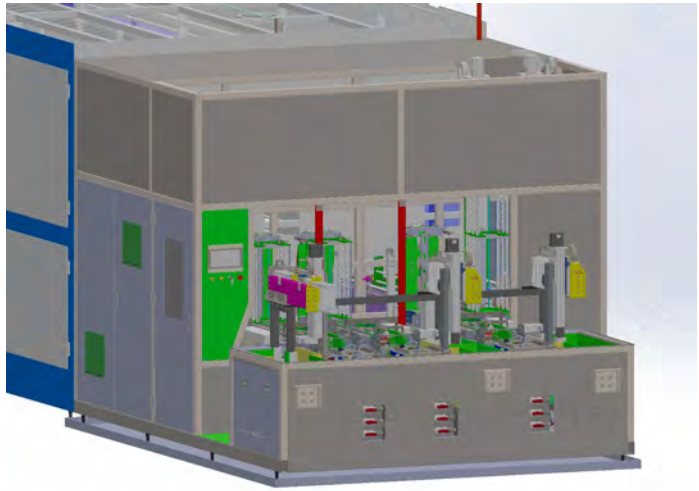
FIT-TJ8C-01A



Equipment performance	• Function: wafer degluing & cleaning after slicing • Principle: ultrasonic + detergent cleaning + rinsing • Process: spray → degluing → rinsing → unloading • Capacity/hour: ≥12 sliced bricks • Power: 150kW • Water consumption (city water): 6m³/hour
Optional Configuration	• Automatic removal of wings • Automatic time adding recognition • Auto wafer picking at unloading point

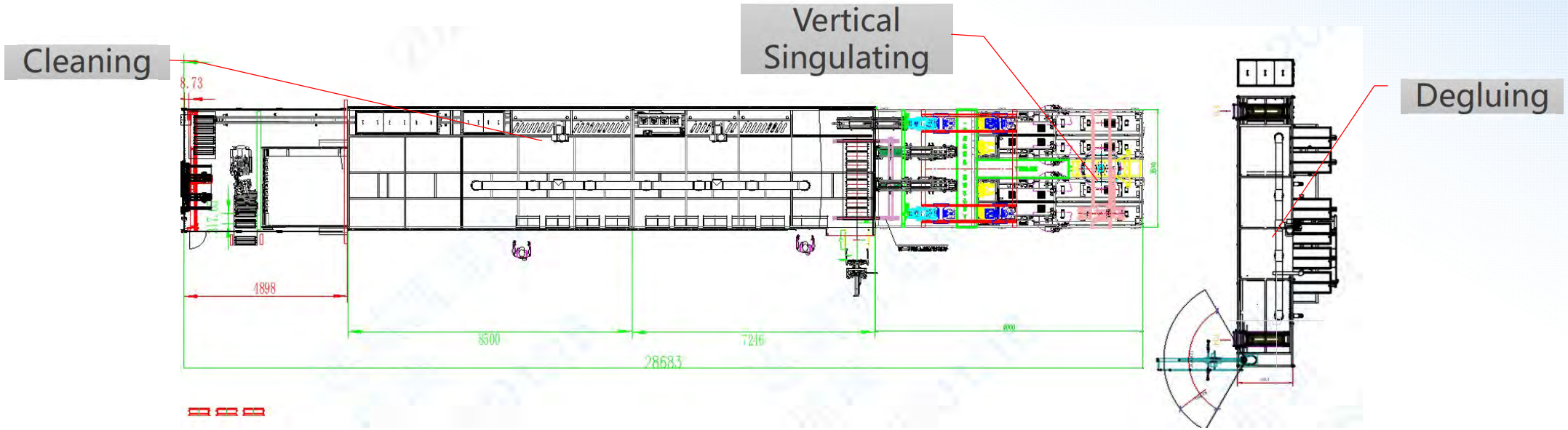
Wafer singulating & cleaning machine

FIT-YT3T15C67LQ-01A



Equipment performance	• Function: wafer singulating & cleaning after slicing • Principle: ultrasonic + detergent cleaning + rinsing + drying • Process: Insert → rinsing → detergent cleaning → rinsing → drying • Capacity/hour: 12000-18000pcs • Power: 530KW • Water consumption (pure water): 1.7m³/hour • Water consumption (city water): 1.5m³/hour
Optional items	• Vacuum drying • Scrap detection • Deformed Cassette detection
High compatiblity	• Compatible with half size wafer with matching cassette • Compatible with double-cassette for half wafer

DEGLUING→SINGULATING→CLEANING ARRANGEMENT



Layout:
Degluing machines are located behind slicing area and connected to the singulating / cleaning line via AGVs.

Equipment Dimensions:
Degluing Machine: L9145 × W3132 × H3624 (mm)
Singulating Machine: L8000 × W3500 × H3577 (mm)
Cleaning Machine: L21000 × W3500 × H3768 (mm) (including blower)

WAFER SORTING MACHINE

Main Specifications:
Power Supply: 380V, 5-lines 3-phase system, 6*5-core cable
Power: 15kW
Air Pressure: 0.5-0.7 MPa
Air Consumption: 550L/min, pipe diameter: Φ16mm
Overall Dimensions: L12300mm×W1600mm×H2039mm
Wafer Size Range: 182×182mm-230×230mm
Wafer Thickness Range: 100-240μm
CT & Production Capacity: CT≤0.18s 20000 pcs/h @182
CT≤0.2s 18000 pcs/h @210

CDA:
Maximum solid particle size: 0.1um
Minimum pressure dew point: -20℃
Maximum oil mist concentration: 0.1mg/m^3

Environmental Requirements:
Temperature: 20℃~25℃
Humidity: 50%~65%
Clean room class: ≤60,000/m^3
(particle count for particles>5μm)

LINTON

Your reliable technical partner and solution provider for your PV Ingot & Wafer projects

Thank you!

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+86 15052260392
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